

8-BIT SINGLE-CHIP MICROCONTROLLER

DESCRIPTION

The μ PD78052, 78053, 78054, 78055, 78056 and 78058 are the μ PD78054 subseries products of the 78K/0 series.

8-bit resolution A/D converter, 8-bit resolution D/A converter, timer, serial interface, real-time output port and interrupt functions.

The μ PD78P054 and 78P058, one-time PROM or EPROM products which can be operated in the same supply voltage range as for the mask ROM product, and various development tools are also available.

Details of the function description, etc, are described in the following User's Manual. Be sure to read it when designing.

μ PD78054, 78054Y Subseries User's Manual: U11747E
78K/0 Series User's Manual Instruction: U12326E

FEATURES

- Large on-chip ROM & RAM

Products Name	Items	Program Memory (ROM)	Data Memory			Package
			Internal High-Speed RAM	Internal Buffer RAM	Internal Expanded RAM	
μ PD78052		16K bytes	512 bytes	32 bytes	No	<ul style="list-style-type: none"> • 80-pin plastic QFP (14 x 14 mm, resin thickness: 2.7 mm) • 80-pin plastic QFP (14 x 14 mm, resin thickness: 1.4 mm) • 80-pin plastic TQFP (fine pitch) (12 x 12 mm)
μ PD78053		24K bytes	1024 bytes			
μ PD78054		32K bytes				
μ PD78055		40K bytes				
μ PD78056		48K bytes				
μ PD78058		60K bytes				

- External memory expansion space: 64K bytes
- Instruction execution time can be varied from high-speed (0.4 μ s) to ultra-low-speed (122 μ s)
- I/O ports: 69 (N-ch open-drain : 4)
- 8-bit resolution A/D converter : 8 channels
- 8-bit resolution D/A converter : 2 channels
- Serial interface : 3 channels
- Timer: 5 channels
- Supply voltage: $V_{DD} = 2.0$ to 6.0 V

APPLICATIONS

Cellular phone, pager, printer, AV equipment, airconditioners, cameras, PPC, fuzzy home appliances, vending machine, etc.

The information in this document is subject to change without notice.

ORDERING INFORMATION

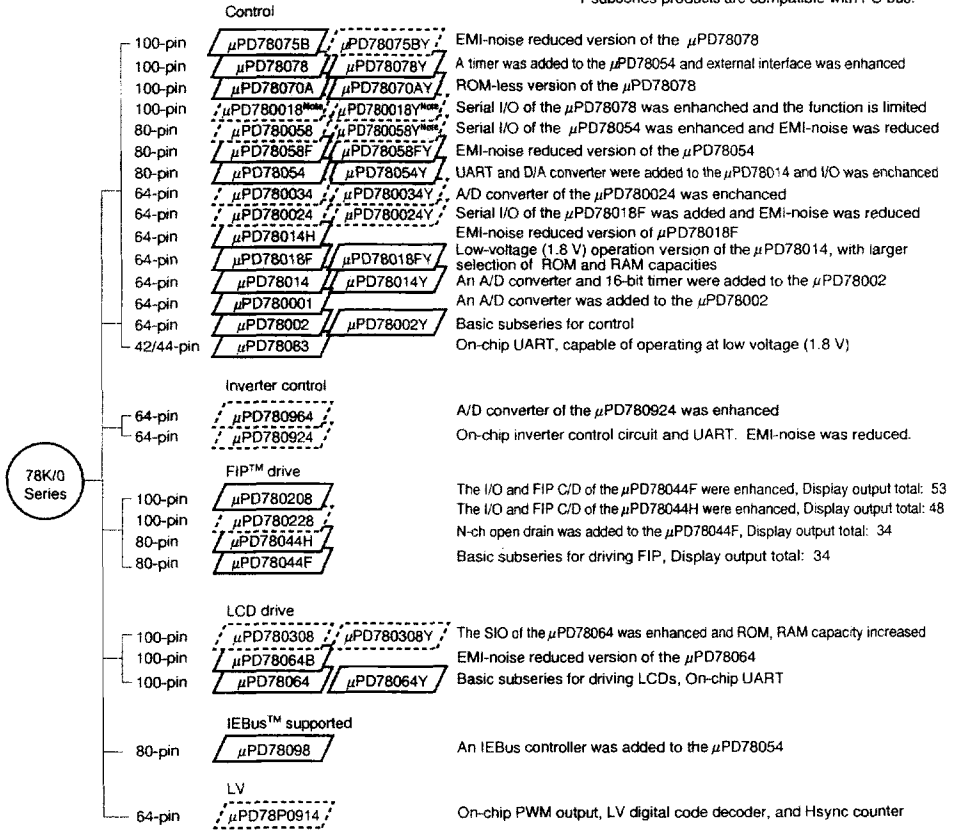
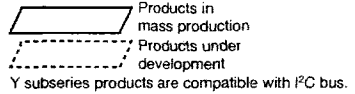
	Part Number	Package
	μPD78052GC-xxx-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
★	μPD78052GC-xxx-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
	μPD78052GK-xxx-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm)
	μPD78053GC-xxx-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
★	μPD78053GC-xxx-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
	μPD78053GK-xxx-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm)
	μPD78054GC-xxx-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
★	μPD78054GC-xxx-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
	μPD78054GK-xxx-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm)
	μPD78055GC-xxx-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
★	μPD78055GC-xxx-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
★	μPD78055GK-xxx-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm)
	μPD78056GC-xxx-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
★	μPD78056GC-xxx-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
★	μPD78056GK-xxx-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm)
	μPD78058GC-xxx-3B9	80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
★	μPD78058GC-xxx-8BT	80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
★	μPD78058GK-xxx-BE9	80-pin plastic TQFP (fine pitch) (12 × 12 mm)

★ Caution μPD78052GC, 78053GC, 78054GC, 78055GC, 78056GC, and 78058GC are available in two types of packages (refer to 13. PACKAGE DRAWINGS). For the available packages, consult NEC.

Remark xxx indicates a ROM code suffix.

★ 78K/0 SERIES PRODUCT DEVELOPMENT

The following shows the 78K/0 Series products development. Subseries name are shown inside frames.



Note Under planning.

The following lists the main functional differences between subseries products.

Subseries Name	Function	ROM Capacity	Timer				8-bit A/D	10-bit A/D	8-bit D/A	Serial Interface	I/O	V _{DD} MIN Value	External Expansion				
			8-bit	16-bit	Watch	WDT											
Control	μ PD78075B	32 K - 40 K	4 ch	1 ch	1 ch	1 ch	8 ch	-	2 ch	3 ch (UART : 1 ch)	88	1.8 V	○				
	μ PD78078	48 K - 60 K									61			2.7 V			
	μ PD78070A	-									88						
	μ PD780018	48 K - 60 K									-	2 ch (time division 3-wire: 1 ch)					
	μ PD780058	24 K - 60 K	2 ch	-	-	-	-	-	2 ch	3 ch (time division UART: 1 ch)	68	1.8 V					
	μ PD78058F	48 K - 60 K									69			2.7 V			
	μ PD78054	16 K - 60 K									2.0 V						
	μ PD780034	8 K - 32 K									-	8 ch		-	3 ch (UART: 1 ch, time division 3-wire: 1 ch)	51	1.8 V
	μ PD780024	8 K - 60 K	-	-	-	-	-	-	8 ch	-	2 ch	53					
	μ PD78014H											2.7 V					
	μ PD78018F											8 K - 60 K		39	-		
	μ PD78014											8 K - 32 K		53			
	μ PD780001	8 K	-	-	-	-	-	-	-	-	1 ch	39		-			
	μ PD78002	8 K - 16 K	-	1 ch	-	-	-	-	-	-	1 ch	53		○			
μ PD78083	-	-	-	-	-	8 ch	-	-	-	1 ch (UART: 1 ch)	33	1.8 V	-				
Inverter control	μ PD780964	8 K - 32 K	3 ch	Note	-	1 ch	-	8 ch	-	2 ch (UART: 2 ch)	47	2.7 V	○				
	μ PD780924	-					8 ch	-									
FIP drive	μ PD780208	32 K - 60 K	2 ch	1 ch	1 ch	1 ch	8 ch	-	-	2 ch	74	2.7 V	-				
	μ PD780228	48 K - 60 K									3 ch			-	-	1 ch	72
	μ PD78044H	32 K - 48 K									2 ch	1 ch		1 ch	68	2.7 V	
	μ PD78044F	16 K - 40 K									2 ch	-		-	2 ch		-
LCD drive	μ PD780308	48 K - 60 K	2 ch	1 ch	1 ch	1 ch	8 ch	-	-	3 ch (time division UART: 1 ch)	57	2.0 V	-				
	μ PD78064B	32 K												2 ch (UART : 1 ch)			
	μ PD78064	16 K - 32 K															
IEBus supported	μ PD78098	32 K - 60 K	2 ch	1 ch	1 ch	1 ch	8 ch	-	2 ch	3 ch (UART : 1 ch)	69	2.7 V	○				
LV	μ PD78P0914	32 K	6 ch	-	-	1 ch	8 ch	-	-	2 ch	54	4.5 V	○				

Note 10-bit timer: 1 channel

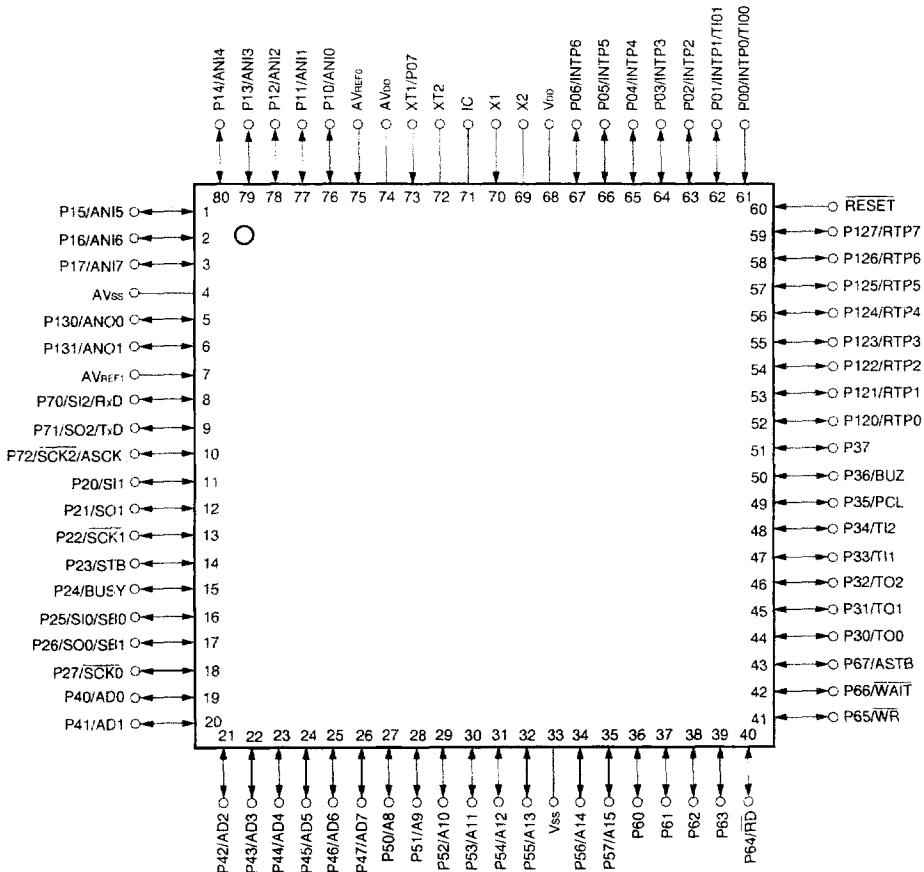
OVERVIEW OF FUNCTION

Item		Product Name													
		μPD78052	μPD78053	μPD78054	μPD78055	μPD78056	μPD78058								
Internal memory	ROM	16K bytes	24K bytes	32K bytes	40K bytes	48K bytes	60K bytes								
	High-speed RAM	512 bytes	1024 bytes												
	Buffer RAM	32 bytes													
	Expanded RAM	None					1024K bytes								
Memory space	64 K bytes														
General registers	8 bits × 32 registers (8 bits × 8 registers × 4 banks)														
Instruction cycle	On-chip instruction execution time cycle modification function														
	When main system clock selected	0.4 μs/0.8 μs/1.6 μs/3.2 μs/6.4 μs/12.8 μs (at 5.0 MHz operation)													
	When subsystem clock selected	122 μs (at 32.768 kHz operation)													
Instruction set	<ul style="list-style-type: none"> • 16-bit operation • Multiplication/division (8 bits × 8 bits, 16 bits ÷ 8 bits) • Bit manipulation (set, reset, test, boolean operation) • BCD correction, etc. 														
I/O ports	<table style="width: 100%; border-collapse: collapse;"> <tr> <td style="text-align: right;">Total</td> <td style="text-align: right;">: 69</td> </tr> <tr> <td style="text-align: right;">• CMOS input</td> <td style="text-align: right;">: 2</td> </tr> <tr> <td style="text-align: right;">• CMOS I/O</td> <td style="text-align: right;">: 63</td> </tr> <tr> <td style="text-align: right;">• N-ch open-drain I/O</td> <td style="text-align: right;">: 4</td> </tr> </table>							Total	: 69	• CMOS input	: 2	• CMOS I/O	: 63	• N-ch open-drain I/O	: 4
Total	: 69														
• CMOS input	: 2														
• CMOS I/O	: 63														
• N-ch open-drain I/O	: 4														
A/D converter	• 8-bit resolution × 8 channels														
D/A converter	• 8-bit resolution × 2 channels														
Serial interface	<ul style="list-style-type: none"> • 3-wire serial I/O/SBI/2-wire serial I/O mode selectable: 1 channel • 3-wire serial I/O mode (on-chip max. 32 bytes automatic data transmit/receive function): 1 channel • 3-wire serial I/O/UART mode selectable : 1 channel 														
Timer	<ul style="list-style-type: none"> • 16-bit timer/event counter : 1 channel • 8-bit timer/event counter : 2 channels • Watch timer : 1 channel • Watchdog timer : 1 channel 														
Timer output	3 (14-bit PWM output × 1)														
Clock output	19.5 kHz, 39.1 kHz, 78.1 kHz, 156 kHz, 313 kHz, 625 kHz, 1.25 MHz, 2.5 MHz, 5.0 MHz (at main system clock 5.0 MHz operation) 32.768 kHz (at subsystem clock 32.768 kHz operation)														
Buzzer output	1.2 kHz, 2.4 kHz, 4.9 kHz, 9.8 kHz (at main system clock 5.0 MHz operation)														
Vectored interrupt sources	Maskable	Internal interrupt : 13, external interrupt : 7													
	Non-maskable	Internal interrupt : 1													
	Software	1													
Test input	Internal : 1, external : 1														
Supply voltage	VDD = 2.0 to 6.0 V														
Operating ambient temperature	T _A = -40 to +85°C														
Package	<ul style="list-style-type: none"> • 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm) • 80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm) • 80-pin plastic TQFP (fine pitch) (12 × 12 mm) 														

★

1. PIN CONFIGURATION (Top View)

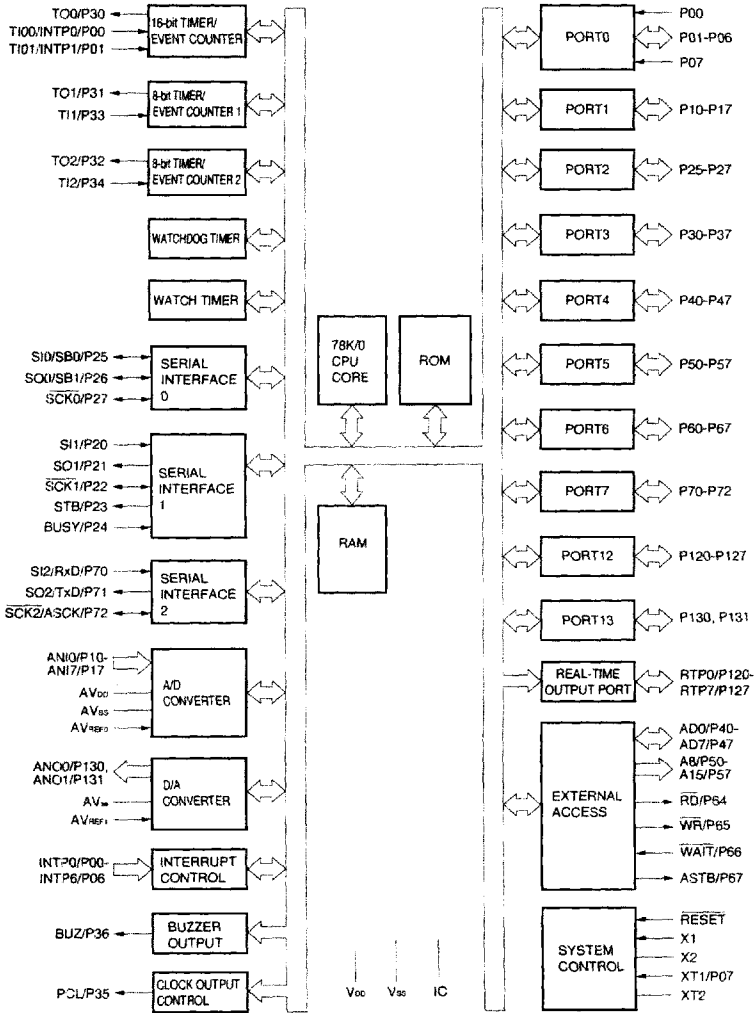
- 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
 μPD78052GC-xxx-3B9, 78053GC-xxx-3B9, 78054GC-xxx-3B9, 78055GC-xxx-3B9,
 μPD78056GC-xxx-3B9, 78058GC-xxx-3B9
- ★ - 80-pin plastic QFP (14 × 14 mm, resin thickness: 1.4 mm)
 μPD78052GC-xxx-8BT, 78053GC-xxx-8BT, 78054GC-xxx-8BT, 78055GC-xxx-8BT,
 μPD78056GC-xxx-8BT, 78058GC-xxx-8BT
- 80-pin plastic TQFP (fine pitch) (12 × 12 mm)
 μPD78052GK-xxx-BE9, 78053GK-xxx-BE9, 78054GK-xxx-BE9, 78055GK-xxx-BE9,
 μPD78056GK-xxx-BE9, 78058GK-xxx-BE9



- Cautions**
1. IC (Internally Connected) pin should be connected directly to Vss.
 2. AVDD pin should be connected to VDD pin.
 3. AVss pin should be connected to Vss pin.

A8-A15	: Address Bus	P130, P131	: Port13
AD0-AD7	: Address/Data Bus	PCL	: Programmable Clock
ANI0-ANI7	: Analog Input	\overline{RD}	: Read Strobe
ANO0, ANO1	: Analog Output	\overline{RESET}	: Reset
ASCK	: Asynchronous Serial Clock	RTP0-RTP7	: Real-Time Output Port
ASTB	: Address Strobe	RxD	: Receive Data
AV _{DD}	: Analog Power Supply	$\overline{SB0, SB1}$: Serial Bus
AV _{REF0} , AV _{REF1}	: Analog Reference Voltage	$\overline{SCK0-SCK2}$: Serial Clock
AV _{SS}	: Analog Ground	SI0-SI2	: Serial Input
BUSY	: Busy	SO0-SO2	: Serial Output
BUZ	: Buzzer Clock	STB	: Strobe
IC	: Internally Connected	TI00, TI01	: Timer Input
INTP0-INTP6	: Interrupt from Peripherals	TI1, TI2	: Timer Input
P00-P07	: Port0	TO0-TO2	: Timer Output
P10-P17	: Port1	TxD	: Transmit Data
P20-P27	: Port2	V _{DD}	: Power Supply
P30-P37	: Port3	V _{SS}	: Ground
P40-P47	: Port4	\overline{WAIT}	: Wait
P50-P57	: Port5	\overline{WR}	: Write Strobe
P60-P67	: Port6	X1, X2	: Crystal (Main System Clock)
P70-P72	: Port7	XT1, XT2	: Crystal (Subsystem Clock)
P120-P127	: Port12		

2. BLOCK DIAGRAM



Remark The internal ROM and RAM capacities differ depending on the product.

3. PIN FUNCTIONS

3.1 Port Pins (1/2)

Pin Name	I/O	Function		After Reset	Dual-Function Pin
P00	Input	Port 0 8-bit I/O port	Input only	Input	INTP0/TI00
P01	Input/ output		Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.	Input	INTP1/TI01
P02					INTP2
P03					INTP3
P04					INTP4
P05					INTP5
P06					INTP6
P07 ^{Note 1}	Input		Input only	Input	XT1
P10 to P17	Input/ output	Port 1 8-bit input/output port. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software. ^{Note 2}		Input	ANI0 to ANI7
P20	Input/ output	Port 2 8-bit input/output port. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.	Input	SI1	
P21				SO1	
P22				SCK1	
P23				STB	
P24				BUSY	
P25				SI0/SB0	
P26				SO0/SB1	
P27				SCK0	
P30	Input/ output	Port 3 8-bit input/output port. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.	Input	TO0	
P31				TO1	
P32				TO2	
P33				TI1	
P34				TI2	
P35				PCL	
P36				BUZ	
P37				---	
P40 to P47	Input/ output	Port 4 8-bit input/output port. Input/output can be specified in 8-bit unit. When used as an input port, pull-up resistor can be used by software. Test input flag (KRIF) is set to 1 by falling edge detection.		Input	AD0 to AD7

- Notes 1.** When using the P07/XT1 pins as an input port, set 1 in the bit 6 (FRC) of the processor clock control register (PCC). On-chip feedback resistor of the subsystem clock oscillator should not be used.
- 2.** When using the P10/ANI0 to P17/ANI7 pins as the A/D converter analog input pins, use of the pull-up resistor is cancelled automatically.

3.1 Port Pins (2/2)

Pin Name	I/O	Function		After Reset	Dual-Function Pin
P50 to P57	Input/output	Port 5 8-bit input/output port. LED can be driven directly. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.		Input	A8 to A15
P60	Input/output	Port 6 8-bit input/output port. Input/output can be specified bit-wise.	N-ch open-drain input/output port. On-chip pull-up resistor can be specified by mask option. LED can be driven directly.	Input	—
P61					
P62					
P63			When used as an input port, pull-up resistor can be used by software.	Input	
P64					
P65					
P66					
P67					
P70	Input/output	Port 7 3-bit input/output port. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.	Input	S12/RxD	
P71				SO2/TxD	
P72				SCK2/ASCK	
P120 to P127	Input/output	Port 12 8-bit input/output port. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.		Input	RTP0 to RTP7
P130, P131	Input/output	Port 13 2-bit input/output port. Input/output can be specified bit-wise. When used as an input port, pull-up resistor can be used by software.		Input	

3.2 Other Pins (1/2)

Pin Name	I/O	Function	After Reset	Dual-Function Pin
INTP0	Input	External interrupt request input by which the effective edge (rising edge, falling edge, or both rising edge and falling edge) can be specified.	Input	P00/TI00
INTP1				P01/TI01
INTP2				P02
INTP3				P03
INTP4				P04
INTP5				P05
INTP6				P06
SI0	Input	Serial interface serial data input.	Input	P25/SB0
SI1				P20
SI2				P70/RxD
SO0	Output	Serial interface serial data output.	Input	P26/SB1
SO1				P21
SO2				P71/TxD
SB0	Input /output	Serial interface serial data input/output.	Input	P25/SI0
SB1				P26/SO0
SCK0	Input /output	Serial interface serial clock input/ output	Input	P27
SCK1				P22
SCK2				P72/ASCK
STB	Output	Serial interface automatic transmit/receive strobe output.	Input	P23
BUSY	Input	Serial interface automatic transmit/receive busy input.	Input	P24
RxD	Input	Asynchronous serial interface serial data input.	Input	P70/SI2
TxD	Output	Asynchronous serial interface serial data output.	Input	P71/SO2
ASCK	Input	Asynchronous serial interface serial clock input.	Input	P72/SCK2
TI00	Input	External count clock input to the 16-bit timer (TM0)	Input	P00/INTP0
TI01		Capture trigger signal input to the capture register (CR00)		P01/INTP1
TI1		External count clock input to the 8-bit timer (TM1)		P33
TI2		External count clock input to the 8-bit timer (TM2)		P34
TO0	Output	16-bit timer (TM0) output (dual-function as 14-bit PWM output)	Input	P30
TO1		8-bit timer (TM1) output		P31
TO2		8-bit timer (TM2) output		P32
PCL	Output	Clock output (for main system clock, subsystem clock trimming).	Input	P35
BUZ	Output	Buzzer output.	Input	P36
RTP0 to RTP7	Output	Real-time output port by which data is output in synchronization with a trigger.	Input	P120 to P127
AD0 to AD7	Input /output	Low-order address/data bus at external memory expansion.	Input	P40 to P47
A8 to A15	Output	High-order address bus at external memory expansion.	Input	P50 to P57
RD	Output	External memory read operation strobe signal output.	Input	P64
WR		External memory write operation strobe signal output.		P65

3.2 Other Pins (2/2)

Pin Name	I/O	Function	After Reset	Dual-Function Pin
WAIT	Input	Wait insertion at external memory access.	Input	P66
ASTB	Output	Strobe output which latches the address information output at port 4 to access external memory.	Input	P67
ANI0 to ANI7	Input	A/D converter analog input.	Input	P10 to P17
ANO0, ANO1	Output	D/A converter analog output.	Input	P130, P131
AVREF0	Input	A/D converter reference voltage input.	—	—
AVREF1	Input	D/A converter reference voltage input.	—	—
AVDD	—	A/D converter analog power supply. Connected to V _{CC}	—	—
AVSS	—	Ground potential of A/D converter and D/A converter. Connected to V _{SS}	—	—
RESET	Input	System reset input.	—	—
X1	Input	Main system clock oscillation crystal connection.	—	—
X2	—		—	—
XT1	Input	Subsystem clock oscillation crystal connection.	Input	P07
XT2	—		—	—
V _{DD}	—	Positive power supply.	—	—
V _{SS}	—	Ground potential.	—	—
IC	—	Internal connection. Connect to V _{SS} directly.	—	—

3.3 Pin I/O Circuits and Recommended Connection of Unused Pins

The input/output circuit type of each pin and recommended connection of unused pins are shown in Table 3-1.

For the input/output circuit configuration of each type, refer to **Figure 3-1**.

Table 3-1. Input/Output Circuit Type of Each Pin (1/2)

Pin Name	Input/output Circuit Type	I/O	Recommended Connection when not Used		
P00/INTP0/TI00	2	Input	Connected to V _{SS} .		
P01/INTP1/TI01	8-A	Input/output	Independently connected to V _{SS} through resistor.		
P02/INTP2					
P03/INTP3					
P04/INTP4					
P05/INTP5					
P06/INTP6					
P07/XT1				16	Input
P10/ANI0 to P17/ANI7	11	Input/output	Independently connected to V _{DD} or V _{SS} through resistor.		
P20/SI1	8-A				
P21/SO1	5-A				
P22/SCK1	8-A				
P23/STB	5-A				
P24/BUSY	8-A				
P25/SI0/SB0	10-A				
P26/SO0/SB1					
P27/SCK0					
P30/TO0	5-A				
P31/TO1					
P32/TO2					
P33/TI1	8-A				
P34/TI2					
P35/PCL	5-A				
P36/BUZ					
P37					
P40/AD0 to P47/AD7	5-E				Independently connected to V _{DD} through resistor.
P50/A8 to P57/A15	5-A				Independently connected to V _{DD} or V _{SS} through resistor.
P60 to P63	13-B				Independently connected to V _{DD} through resistor.
P64/ \overline{RD}	5-A				Independently connected to V _{DD} or V _{SS} through resistor.
P65/ \overline{WR}					
P66/ \overline{WAIT}					
P67/ASTB					

Table 3-1. Input/Output Circuit Type of Each Pin (2/2)

Pin Name	Input/output Circuit Type	I/O	Recommended Connection when not Used
P70/SI2/RxD	8-A	Input/ output	Independently connected to V _{DD} or V _{SS} through resistor.
P71/SO2/TxD	5-A		
P72/SCK2/ASC<	8-A		
P120/RTP0 to P127/RTP7	5-A	input/ output	
P130/AN00 P131/AN01	12-A	Input/ output	Independently connected to V _{SS} through resistor.
RESET	2	Input	—
XT2	16	—	Leave open.
AVREF0	—		Connected to V _{SS} .
AVREF1			Connected to V _{DD} .
AVDD			
AVSS			Connected to V _{SS} .
IC			Connected to V _{SS} directly.

Figure 3-1. Pin Input/Output Circuits (1/2)

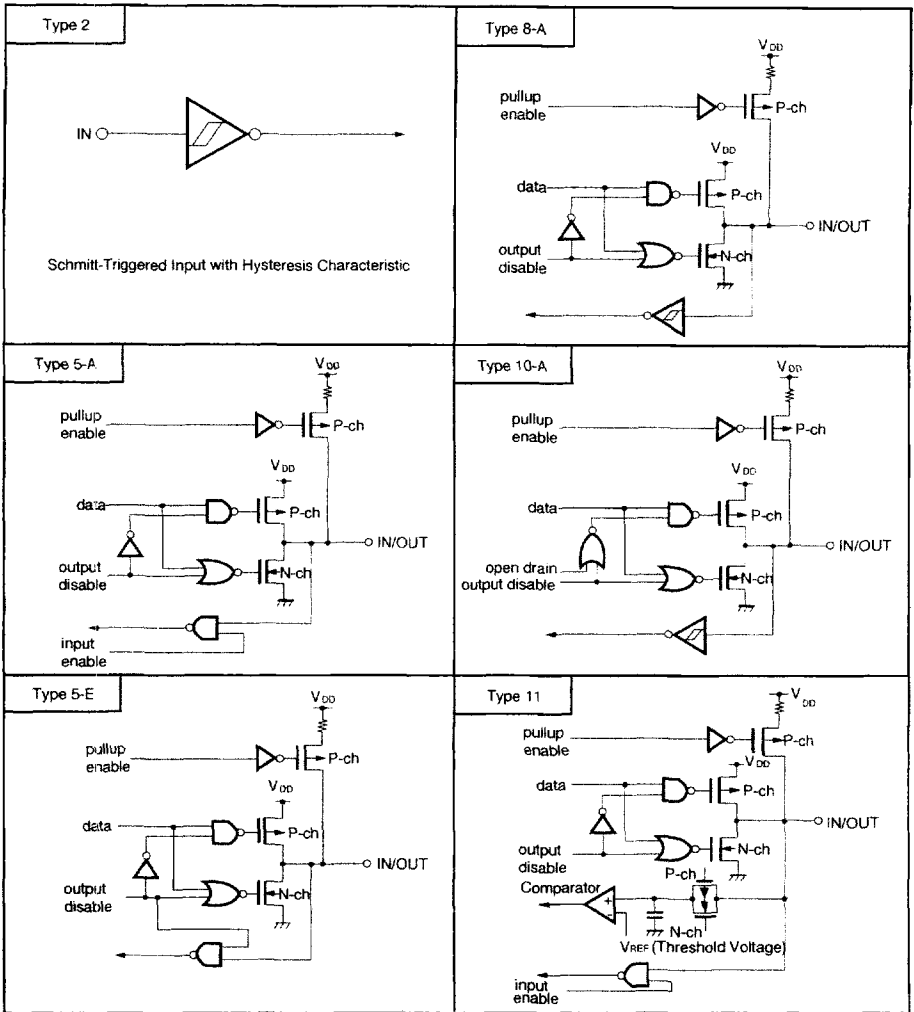
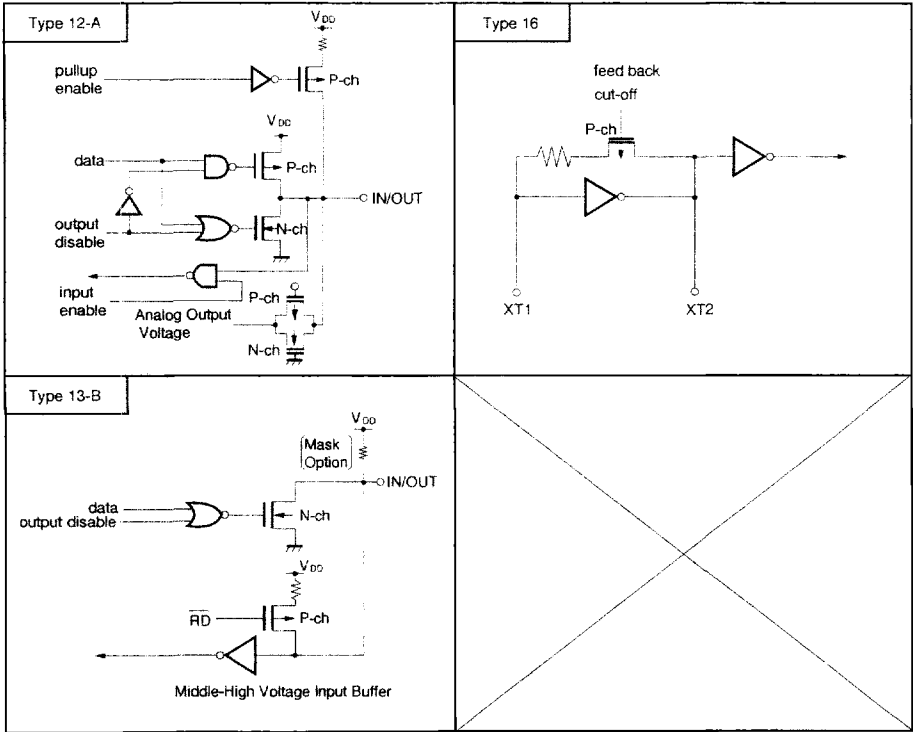


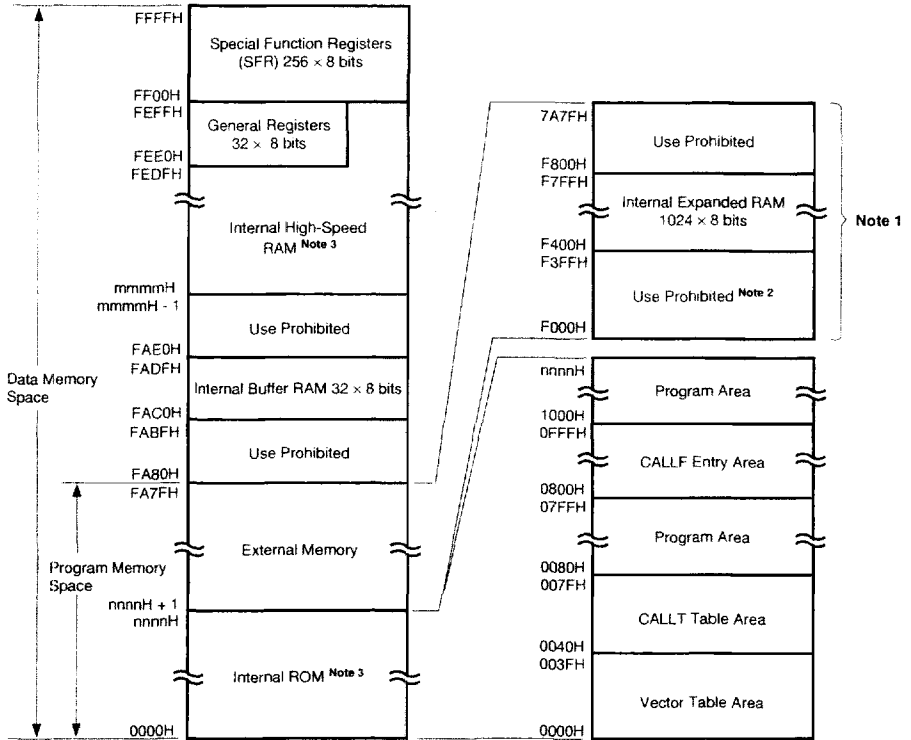
Figure 3-1. Pin Input/Output Circuits (2/2)



4. MEMORY SPACE

Figure 4-1 shows the μPD78052/78053/78054/78055/78056/78058 memory map.

Figure 4-1. Memory Map



Notes 1. μPD78058 only

- When the external device expansion function is used with the μPD78058, set the internal ROM capacity to 56K bytes or less using the memory size switching register (IMS).
- The internal ROM capacity and internal high-speed RAM capacity depend on the products (see the next table).

Relevant Product Name	Internal ROM Last Address nnnnH	Internal RAM First Address mmmmH
μPD78052	3FFFH	FD00H
μPD78053	5FFFH	FB00H
μPD78054	7FFFH	
μPD78055	9FFFH	
μPD78056	BFFFH	
μPD78058	EFFFH	

5. PERIPHERAL HARDWARE FUNCTION FEATURES

5.1 Ports

The following 3 types of I/O ports are available.

• CMOS input (P00, P07)	: 2
• CMOS input/output (P01 to P06, port 1 to port 5, P64 to P67, port 7, port 12, port 13)	: 63
• N-channel open-drain input/output (P60 to P63)	: 4
Total:	: 69

Table 5-1. Port Functions

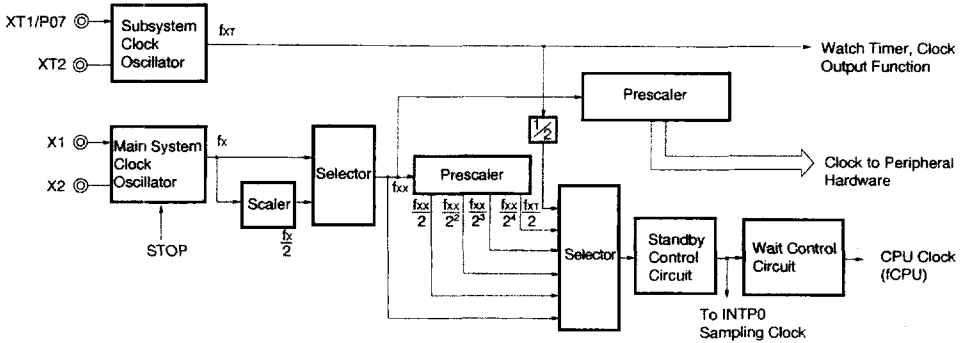
Name	Pin Name	Function
Port 0	P00, P07	Dedicated input port pins
	P01 to P06	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 1	P10 to P17	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 2	P20 to P27	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 3	P30 to P37	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 4	P40 to P47	Input/output port pins. Input/output specifiable in 8-bit units. When used as input port pins, on-chip pull-up resistor can be used by software. Test flag (KRIF) is set to 1 by falling edge detection.
Port 5	P50 to P57	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software. LED direct drive capability.
Port 6	P60 to P63	N-channel open-drain input/output port pins. Input/output specifiable bit-wise. On-chip pull-up resistor can be used by mask option. LED direct drive capability.
	P64 to P67	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 7	P70 to P72	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 12	P120 to P127	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.
Port 13	P130, P131	Input/output port pins. Input/output specifiable bit-wise. When used as input port pins, on-chip pull-up resistor can be used by software.

5.2 Clock Generator

Two types of generators, a main system clock generator and a subsystem clock generator, are available. The instruction execution time can also be changed.

- 0.4 μs/0.3 μs/1.6 μs/3.2 μs/6.4 μs/12.8 μs (main system clock: at 5.0 MHz operation)
- 122 μs (subsystem clock: at 32.768 kHz operation)

Figure 5-1. Clock Generator Block Diagram



5.3 Timer/Event Counter

The μPD78052/78053/78054/78055/78056/78058 incorporate 5 channels of the timer/event counter.

- 16-bit timer/event counter : 1 channel
- 8-bit timer/event counter : 2 channels
- Watch timer : 1 channel
- Watchdog timer : 1 channel

Table 5-2. Types and Functions of Timer/Event Counter

	16-Bit Timer/Event Counter	8-Bit Timer/Event Counter	Watch Timer	Watchdog Timer
Type				
Interval timer	1 channel	2 channels	1 channel	1 channel
External event counter	1 channel	2 channels	—	—
Function				
Timer output	1 output	2 outputs	—	—
PWM output	1 output	—	—	—
Pulse amplitude measurement	2 inputs	—	—	—
Square wave output	1 output	2 outputs	—	—
Ono-shot pulse output	1 output	—	—	—
★ Interrupt source	2	2	1	1
★ Test input	—	—	1 input	—

Figure 5-2. 16-Bit Timer/Event Counter Block Diagram

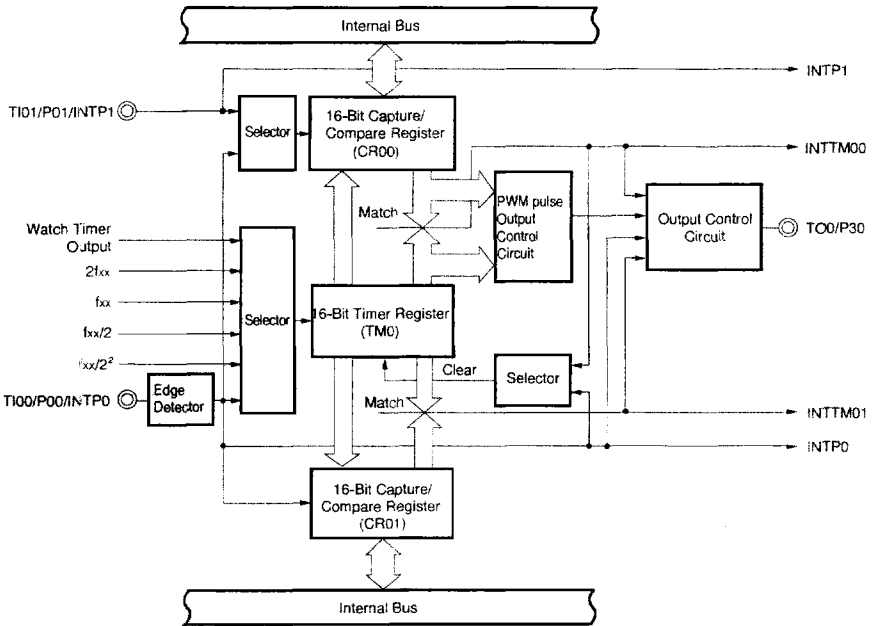


Figure 5-3. 8-Bit Timer/Event Counter Block Diagram

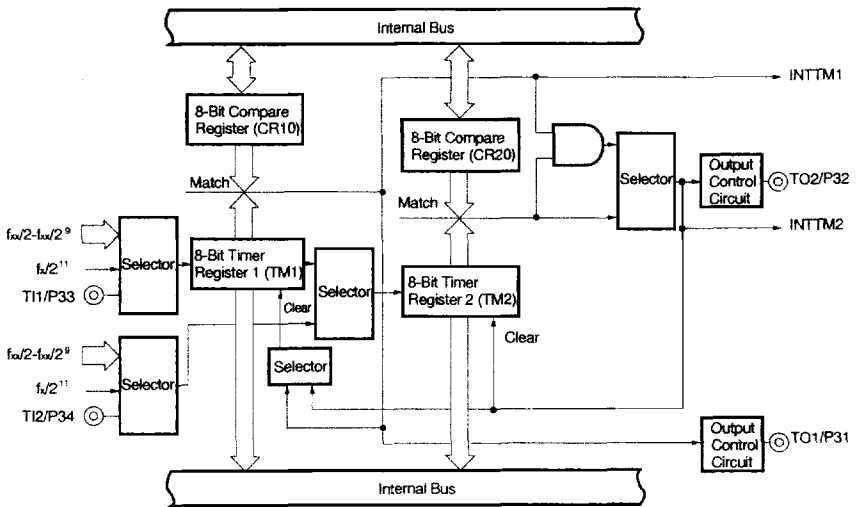


Figure 5-4. Watch Timer Block Diagram

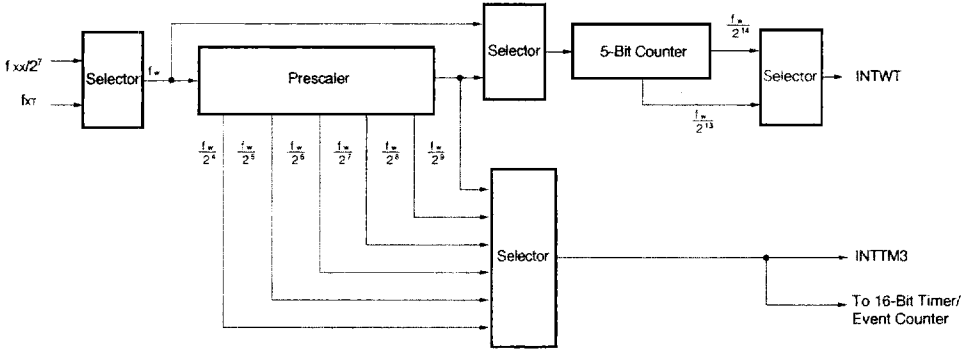
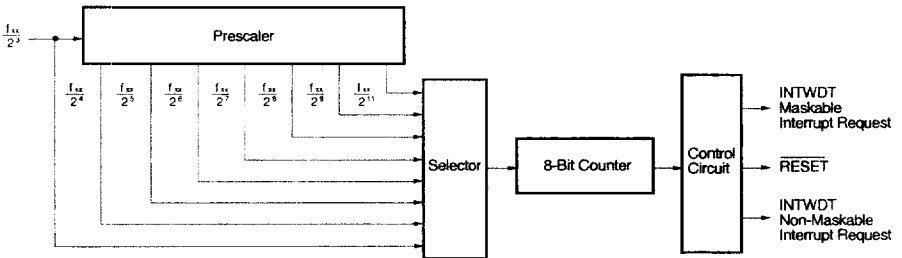


Figure 5-5. Watchdog Timer Block Diagram

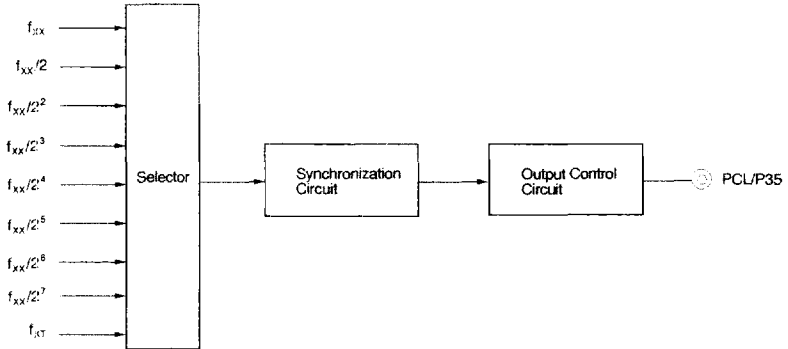


5.4 Clock Output Control Circuit

The clock with the following frequency can be output as a clock output.

- 19.5 kHz/39.1 kHz/78.1 kHz/156 kHz/313 kHz/625 kHz/1.25 MHz/2.5 MHz/5.0 MHz (main system clock: at 5.0 MHz operation)
- 32.768 kHz (subsystem clock: at 32.768 kHz operation)

Figure 5-6. Clock Output Control Circuit Configuration

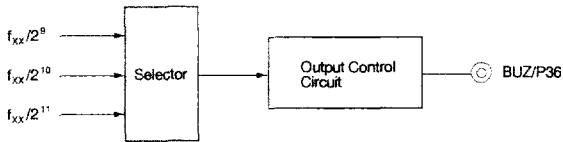


5.5 Buzzer Output Control Circuit

The clock with the following frequency can be output as a buzzer output.

- 1.2 kHz/2.4 kHz/4.9 kHz/9.8 kHz (main system clock: at 5.0 MHz operation)

Figure 5-7. Buzzer Output Control Circuit Block Diagram



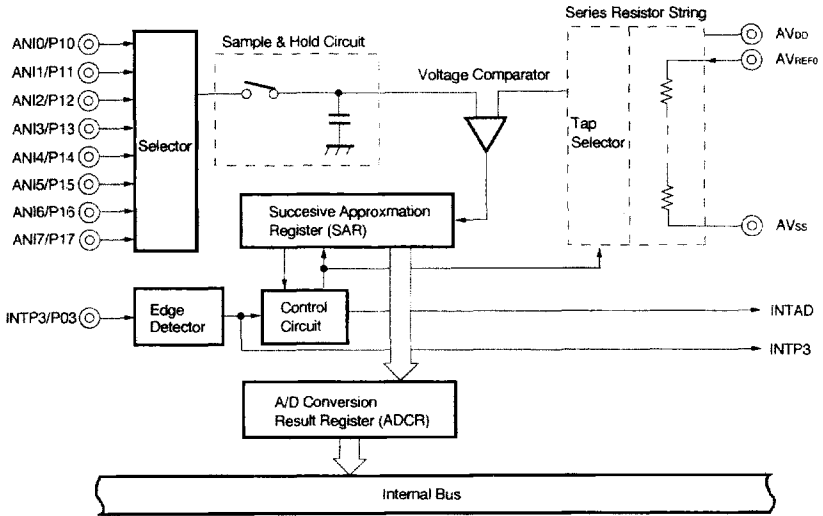
5.6 A/D Converter

An A/D converter of 8-bit resolution × 8 channels is incorporated.

The following two types of the A/D conversion operation start-up methods are available.

- Hardware start
- Software start

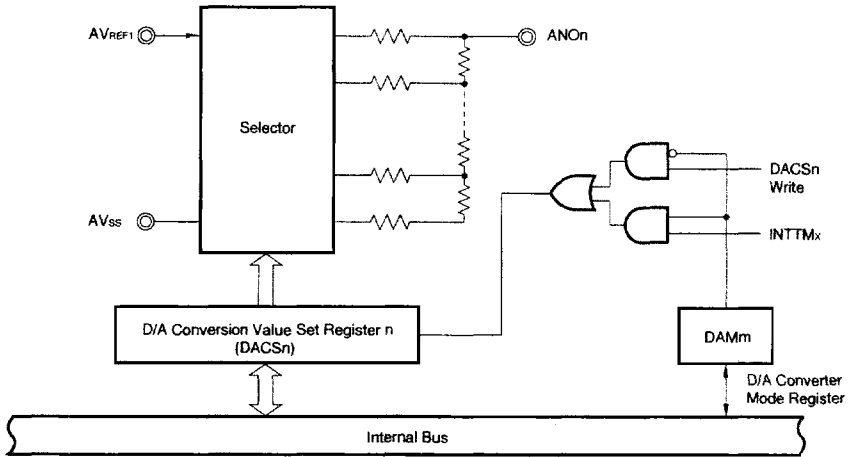
Figure 5-8. A/D Converter Block Diagram



5.7 D/A Converter

A D/A converter of 8-bit resolution × 2 channels is available.
Conversion method is R-2R resistor ladder method.

Figure 5-9. D/A Converter Block Diagram



n = 0, 1
m = 4, 5
x = 1, 2

5.8 Serial Interfaces

3 channels of the clocked serial interface are incorporated.

- Serial interface channel 0
- Serial interface channel 1
- Serial interface channel 2

Table 5-3. Types and Functions of Serial Interface

Function	Serial Interface Channel 0	Serial Interface Channel 1	Serial Interface Channel 2
3-wire serial I/O mode	○ (MSB/LSB first switchable)	○ (MSB/LSB first switchable)	○ (MSB/LSB first switchable)
3-wire serial I/O mode with automatic transmit/receive function	—	○ (MSB/LSB first switchable)	—
SBI (serial bus interface) mode	○ (MSB first)	—	—
2-wire serial I/O mode	○ (MSB first)	—	—
Asynchronous serial interface (UART) mode	—	—	○ (Dedicated baud rate generator incorporated)

Figure 5-10. Serial Interface Channel 0 Block Diagram

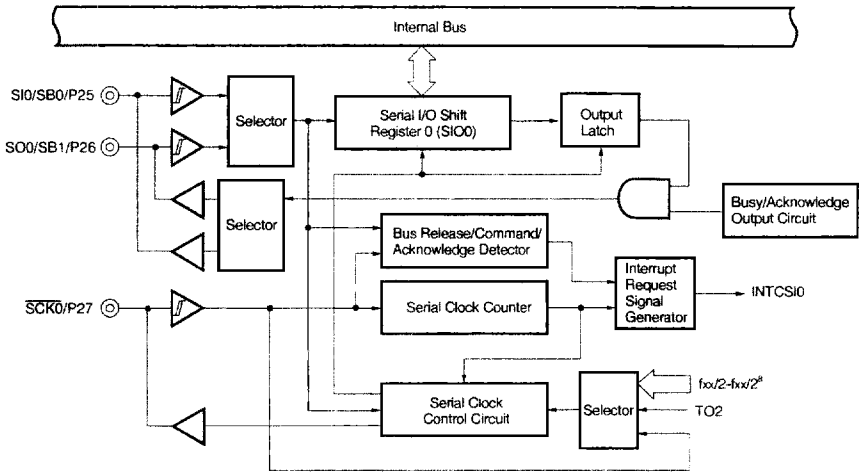


Figure 5-11. Serial Interface Channel 1 Block Diagram

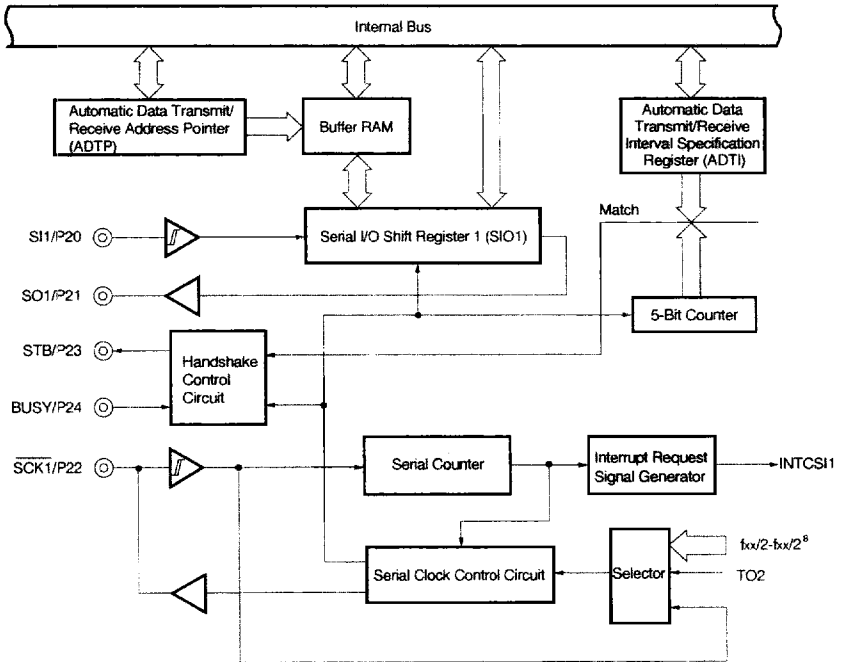
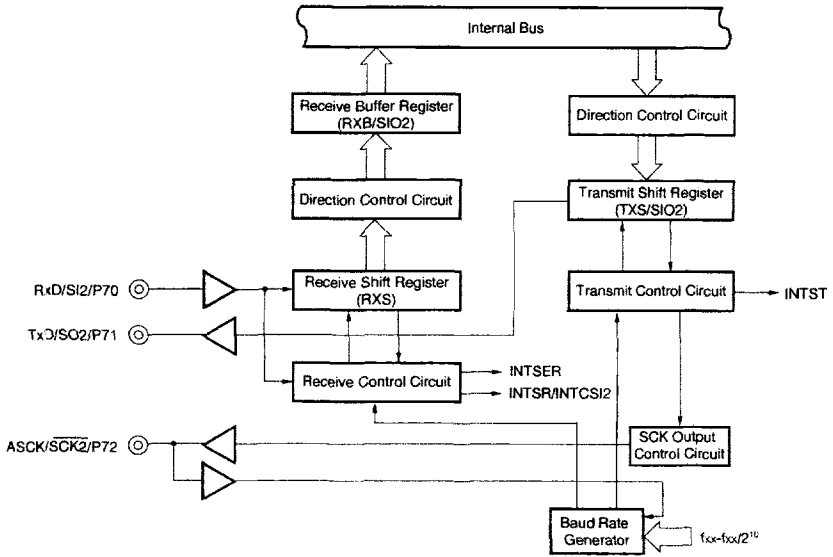


Figure 5-12. Serial Interface Channel 2 Block Diagram

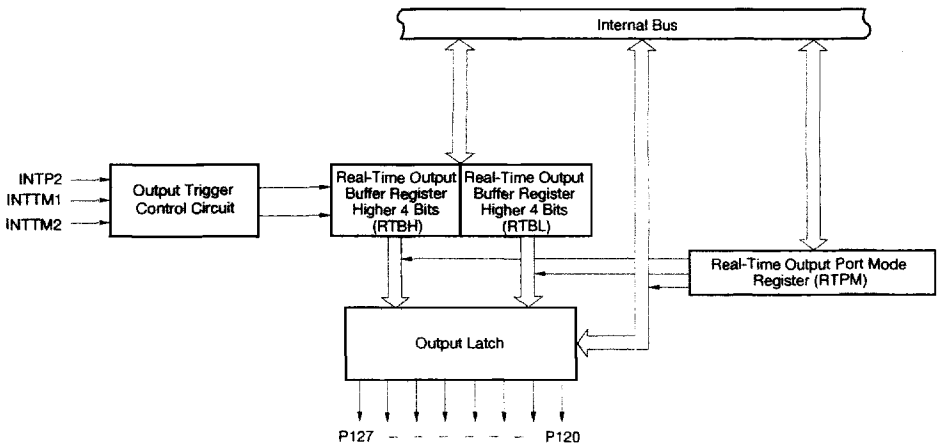


5.9 Real-Time Output Port Functions

Data set previously in the real-time output buffer register is transferred to the output latch by hardware concurrently with timer interrupt and external interrupt generation in order to output to off-chip. This is real-time output function. And pins to output to off-chip are called real-time output ports.

By using a real-time output port, a signal which has no jitter can be output. This is most applicable to control of stepping motor, etc.

Figure 5-13. Real-Time Output Port Block Diagram



6. INTERRUPT FUNCTIONS AND TEST FUNCTIONS

6.1 Interrupt Functions

There are interrupt functions, 22 sources of three different kinds, as shown below.

- Non-maskable : 1
- Maskable : 20
- Software : 1

Table 6-1. Interrupt Source List (1/2)

Interrupt Type	Default ^{Note 1} Priority	Interrupt Source		Internal/ External	Vector Table Address	Basic Configuration Type ^{Note 2}				
		Name	Trigger							
Non-maskable	—	INTWDT	Watchdog timer overflow (watchdog timer mode 1 selected)	Internal	0004H	(A)				
Maskable	0	INTWDT	Watchdog timer overflow (interval timer mode selected)			External	0006H	(B)		
	1	INTP0	Pin input edge detection	0008H	(D)					
	2	INTP1								
	3	INTP2								
	4	INTP3								
	5	INTP4								
	6	INTP5								
	7	INTP6								
	8	INTCSI0						End of serial interface channel 0 transfer	Internal	0014H
	9	INTCSI1	End of serial interface channel 1 transfer							
	10	INTSER	Generation of serial interface channel 2 UART receive error	0016H	0018H					
								11		
	INTCSI2	End of serial interface channel 2 3-wire transfer								
12	INTST	End of serial interface channel 2 UART transmission	001CH							

- Notes**
1. The default priority is a priority order when two or more maskable interrupts are generated simultaneously. 0 is the highest order and 18, the lowest.
 2. Basic configuration types (A) to (E) correspond to A to E in Figure 6-1, respectively.

Table 6-1. Interrupt Source List (2/2)

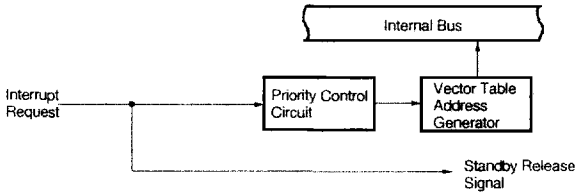
Interrupt Type	Default ^{Note 1} Priority	Interrupt Source		Internal/ External	Vector Table Address	Basic Configuration Type ^{Note 2}
		Name	Trigger			
Maskable	13	INTTM3	Reference time interval signal from watch timer	Internal	001EH	(B)
	14	INTTM00	Generation of match signal of 16-bit timer register and capture/compare register (CR00)		0020H	
	15	INTTM01	Generation of match signal of 16-bit timer register and capture/compare register (CR01)		0022H	
	16	INTTM1	Generation of match signal of 8-bit timer/event counter 1		0024H	
	17	INTTM2	Generation of match signal of 8-bit timer/event counter 2		0026H	
	18	INTAD	End of conversion by A/D converter		0028H	
Software	—	BRK	BRK instruction execution	—	003EH	(E)

Notes 1. The default priority is a priority order when two or more maskable interrupts are generated simultaneously. 0 is the highest order and 18, the lowest.

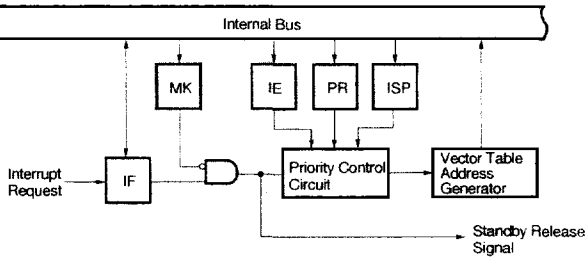
2. Basic configuration types (A) to (E) correspond to (A) to (E) in Figure 6-1, respectively.

Figure 6-1. Interrupt Function Basic Configuration (1/2)

(A) Internal non-maskable interrupt



(B) Internal maskable interrupt



(C) External maskable interrupt (INTP0)

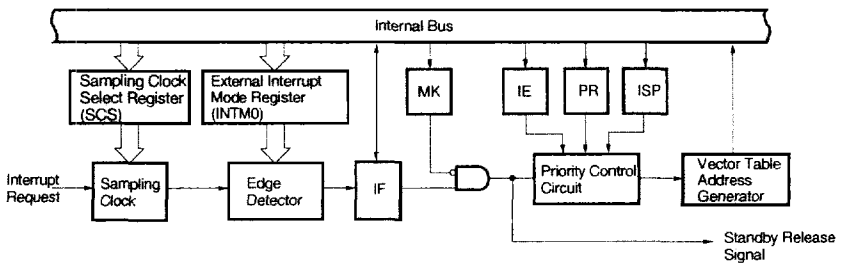
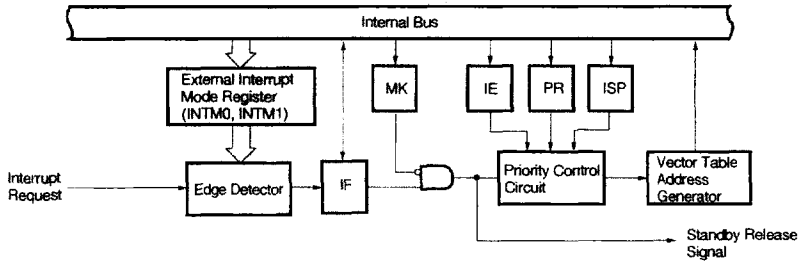
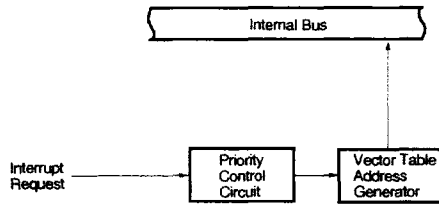


Figure 6-1. Interrupt Function Basic Configuration(2/2)

(D) External maskable interrupt (except INTP0)



(E) Software interrupt



- IF : Interrupt request flag
- IE : Interrupt enable flag
- ISP : In-service priority flag
- MK : Interrupt mask flag
- PR : Priority specification flag

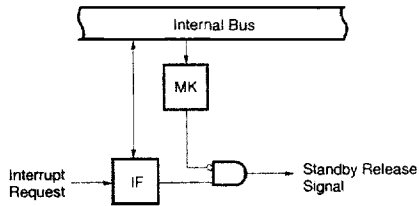
6.2 Test Functions

There are two test functions as shown in Table 6-2.

Table 6-2. Test Input Source List

Test Input Source		Internal/External
Name	Trigger	
INTWT	Watch timer overflow	Internal
INTPT4	Port 4 falling edge detection	External

Figure 6-2. Test Function Basic Configuration



IF : Test input flag

MK : Test mask flag

7. EXTERNAL DEVICE EXPANSION FUNCTIONS

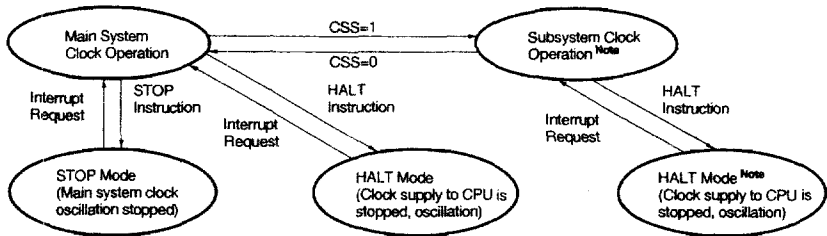
The external device expansion functions connect external devices to areas other than the internal ROM, RAM and SFR. Ports 4 to 6 are used for external device connection.

8. STANDBY FUNCTION

There are the following two standby functions to reduce the system power consumption.

- HALT mode : The CPU operating clock is stopped.
The average consumption current can be reduced by intermittent operation in combination with the normal operating mode.
- STOP mode : The main system clock oscillation is stopped. The whole operation by the main system clock is stopped, so that the system operates with ultra-low power consumption using only the subsystem clock.

Figure 8-1. Stand-by Function



Note The power consumption can be reduced by stopping the main system clock. When the CPU is operating on the subsystem clock, set the bit 7 (MCC) of the processor clock control register (PCC) to stop the main system clock. The STOP instruction cannot be used.

Caution When the main system clock is stopped and the system is operated by the subsystem clock, the subsystem clock should be switched again to the main system clock after the oscillation stabilization time is secured in software.

9. RESET FUNCTION

There are the following two reset methods.

- External reset input by $\overline{\text{RESET}}$ pin
- Internal reset by watchdog timer hung-up time detection

10. INSTRUCTION SET

(1) 8-bit instruction

MOV, XCH, ADD, ADDC, SUB, SUBC, AND, OR, XOR, CMP, MULU, DIVUW, INC, DEC, ROR, ROL, RORC, ROLC, ROR4, ROL4, PUSH, POP, DBNZ

Second Operand First Operand	#byte	A	r Note	sfr	saddr	laddr16	PSW	[DE]	[HL]	[HL + Byte] [HL + B] [HL + C]	Saddr16	1	None
A	ADD ADDC SUB SUBC AND OR XOR CMP		MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP	MOV XCH	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP	MOV XCH	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP	MOV XCH ADD ADDC SUB SUBC AND OR XOR CMP			ROR ROL RORC ROLC	
r	MOV	MOV ADD ADDC SUB SUBC AND OR XOR CMP											INC DEC
★													
B, C											DBNZ		
sfr	MOV	MOV											
saddr	MOV ADD ADDC SUB SUBC AND OR XOR CMP	MOV									DBNZ		INC DEC
laddr16		MOV											
PSW	MOV	MOV											PUSH POP
[DE]		MOV											
[HL]		MOV											ROR4 ROL4
[HL + Byte] [HL + B] [HL + C]		MOV											
X													MULU
C													DIVUW

Note Except r = A

(2) 16-bit instruction

MOV, XCHW, ADDW, SUBW, CMPW, PUSH, POP, INCW, DECW

Second instruction First instruction	#word	AX	rp ^{Note}	sfrp	saddrp	!addr16	SP	None
AX	ADDW SUBW CMPW		MOVW XCHW	MOVW	MOVW	MOVW	MOVW	
rp	MOVW	MOVW ^{Note}						INCW, DECW PUSH, POP
sfrp	MOVW	MOVW						
saddrp	MOVW	MOVW						
!addr16		MOVW						
SP	MOVW	MOVW						

Note Only when rp = BC, DE or HL

(3) Bit manipulation instruction

MOV1, AND1, OR1, XOR1, SET1, CLR1, NOT1, BT, BF, BTCLR

Second instruction First instruction	A.bit	sfr.bit	saddr.bit	PSW.bit	[HL].bit	CY	Saddr16	None
A.bit						MOV1	BT BF BTCLR	SET1 CLR1
sfr.bit						MOV1	BT BF BTCLR	SET1 CLR1
saddr.bit						MOV1	BT BF BTCLR	SET1 CLR1
PSW.bit						MOV1	BT BF BTCLR	SET1 CLR1
[HL].bit						MOV1	BT BF BTCLR	SET1 CLR1
CY	MOV1 AND1 OR1 XOR1	MOV1 AND1 OR1 XOR1	MOV1 AND1 OR1 XOR1	MOV1 AND1 OR1 XOR1	MOV1 AND1 OR1 XOR1			SET1 CLR1 NOT1

(4) Call instruction/branch instruction

CALL, CALLF, CALLT, BR, BC, BNC, BZ, BNZ, BT, BF, BTCLR, DBNZ

Second instruction First instruction	AX	!addr16	!addr11	[addr5]	Saddr16
Basic instruction	BR	CALL BR	CALLF	CALLT	BR, BC, BNC BZ, BNZ
Compound instruction					BT, BF BTCLR DBNZ

(5) Other instructions

ADJBA, ADJBS, BRK, RET, RETI, RETB, SEL, NOP, EI, DI, HALT, STOP

11. ELECTRICAL SPECIFICATIONS

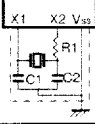
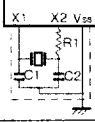
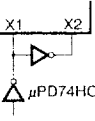
Absolute Maximum Ratings (T_A = 25 °C)

Parameter	Symbol	Test Conditions		Rating	Unit	
Supply voltage	V _{DD}			-0.3 to +7.0	V	
	AV _{DD}			+0.3 to V _{DD} +0.3	V	
	AV _{REF0}			-0.3 to V _{DD} +0.3	V	
	AV _{REF1}			-0.3 to V _{DD} +0.3	V	
	AV _{SS}			-0.3 to +0.3	V	
Input voltage	V _{I1}	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P72, P120 to P127, P130, P131, X1, X2, XT2, RESET		-0.3 to V _{DD} +0.3	V	
	V _{I2}	P60 to P63	N-ch Open-drain	-0.3 to +16	V	
Output voltage	V _O			-0.3 to V _{DD} +0.3	V	
Analog input voltage	V _{AN}	P10 to P17	Analog input pin	AV _{SS} -0.3 to AV _{REF0} +0.3	V	
Output current high	I _{OH}	1 pin		-10	mA	
		P01 to P06, P30-P37, P56, P57, P60 to P67, P120 to P127 total		-15	mA	
		P10 to P17, P20 to P27, P40 to P47, P50 to P55, P70 to P72, P130, P131 total		-15	mA	
Output current low	I _{OL} ^{Note 2}	1 pin		Peak value	30	mA
				rms value	15	mA
		P50 to P55 total		Peak value	100	mA
				rms value	70	mA
		P56, P57, P60 to P63 total		Peak value	100	mA
				rms value	70	mA
		P10 to P17, P20 to P27, P40 to P47, P70 to P72, P130, P131 total		Peak value	50	mA
				rms value	20	mA
P01 to P06, P30 to P37, P64 to P67, P120 to P127 total		Peak value	50	mA		
		rms value	20	mA		
Operating ambient temperature	T _A			-40 to +85	°C	
Storage temperature	T _{stg}			-65 to +150	°C	

Note rms value should be calculated as follows: [rms value] = [Peak value] × √duty

Caution Product quality may suffer if the absolute maximum rating is exceeded for even a single parameter or even momentarily. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions which ensure that the absolute maximum ratings are not exceeded.

Main System Clock Oscillation Circuit Characteristics (T_a = -40 to +85 °C, V_{DD} = 2.0 to 6.0 V)

Resonator	Recommended Circuit	Parameter	Test Conditions	MIN.	TYP.	MAX.	Unit
Ceramic resonator		Oscillator frequency (f _x) <i>Note 1</i>	V _{DD} = Oscillator voltage range	1.0		5.0	MHz
		Oscillation stabilization time <i>Note 2</i>	After V _{DD} reaches oscillator voltage range MIN.			4	ms
Crystal resonator		Oscillator frequency (f _x) <i>Note 1</i>		1.0		5.0	MHz
		Oscillation stabilization time <i>Note 2</i>	V _{DD} = 4.5 to 6.0 V			10	ms
External clock		X1 input frequency (f _x) <i>Note 1</i>		1.0		5.0	MHz
		X1 input high/low level width (t _{OH} , t _{OL})		85		500	ns

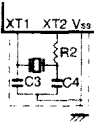
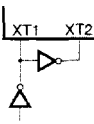
- Notes 1.** Indicates only oscillation circuit characteristics. Refer to **AC Characteristics** for instruction execution time.
2. Time required to stabilize oscillation after reset or STOP mode release.

Cautions 1. When using the main system clock oscillator, wiring in the area enclosed with the broken line should be carried out as follows to avoid an adverse effect from wiring capacitance.

- Wiring should be as short as possible.
- Wiring should not cross other signal lines.
- Wiring should not be placed close to a varying high current.
- The potential of the oscillator capacitor ground should be the same as V_{SS}.
- Do not ground wiring to a ground pattern in which a high current flows.
- Do not fetch a signal from the oscillator.

2. When the main system clock is stopped and the system is operated by the subsystem clock, the subsystem clock should be switched again to the main system clock after the oscillation stabilization time is secured in software.

Subsystem Clock Oscillation Circuit Characteristics (T_A = -40 to +85 °C, V_{DD} = 2.0 to 6.0 V)

Resonator	Recommended Circuit	Parameter	Test Conditions	MIN.	TYP.	MAX.	Unit
Crystal resonator		Oscillator frequency (f _{XT1}) Note 1		32	32.768	35	kHz
		Oscillation stabilization time Note 2	V _{DD} = 4.5 to 6.0 V		1.2	2	s
External clock		XT1 input frequency (f _{XT1}) Note 1		32		100	kHz
		XT1 input high/low level width (t _{XTH} , t _{XTL})		5		15	μs

- Notes**
1. Indicates only oscillation circuit characteristics. Refer to **AC Characteristics** for instruction execution time.
 2. Time required to stabilize oscillation after V_{DD} reaches oscillator voltage MIN.

Cautions 1. When using the subsystem clock oscillator, wiring in the area enclosed with the broken line should be carried out as follows to avoid an adverse effect from wiring capacitance.

- Wiring should be as short as possible.
- Wiring should not cross other signal lines.
- Wiring should not be placed close to a varying high current.
- The potential of the oscillator capacitor ground should be the same as V_{SS}.
- Do not ground wiring to a ground pattern in which a high current flows.
- Do not fetch a signal from the oscillator.

2. The subsystem clock oscillation circuit is a circuit with a low amplification level, more prone to misoperation due to noise than the main system clock.

Recommended Oscillation Circuit Constant

(1) μPD78052, 78053, 78054, 78055, 78056

Main system clock: ceramic resonator (T_A = -40 to +85 °C)

Manufacturer	Product Name	Frequency (MHz)	Recommended Circuit Constant			Oscillator Voltage Range		Remarks
			C1 (pF)	C2 (pF)	R1 (kΩ)	MIN. (V)	MAX. (V)	
Murata Mfg. Co., Ltd.	CSA5.00MG	5.00	30	30	0	2.0	6.0	
	CST5.00MGW	5.00	On chip	On chip	0	2.0	6.0	Capacitor on chip
Kyocera Corp.	KBR-5.0MSA	5.00	33	33	0	2.0	6.0	Lead type
	KBR-5.0MKS	5.00	On chip	On chip	0	2.0	6.0	Capacitor on chip, lead type
	KBR-5.0MWS	5.00	On chip	On chip	0	2.0	6.0	Capacitor on chip, lead type
	PBRC 5.00A	5.00	33	33	0	2.0	6.0	Chip type
TDK Corp.	CCR4.0MC3	4.00	On chip	On chip	0	2.0	6.0	Capacitor on chip
	CCR5.0MC3	5.00	On chip	On chip	0	2.0	6.0	Capacitor on chip

Main system clock: crystal resonator (T_A = -10 to +70 °C)

Manufacturer	Product Name	Frequency (MHz)	Recommended Circuit Constant			Oscillator Voltage Range	
			C1 (pF)	C2 (pF)	R1 (kΩ)	MIN. (V)	MAX. (V)
Daishinku Corp.	SMD-49	3.579545	27	27	1.5	2.0	6.0

Subsystem clock: crystal resonator (T_A = -10 to +70 °C)

Manufacturer	Product Name	Frequency (MHz)	Recommended Circuit Constant			Oscillator Voltage Range	
			C3 (pF)	C4 (pF)	R2 (kΩ)	MIN. (V)	MAX. (V)
Daishinku Corp.	DT-38 (1TA252E00)	32.768	27	20	330	2.0	6.0

Caution The oscillation circuit constants and oscillation voltage range indicate conditions for stable oscillation. However, they do not guarantee accuracy of the oscillation frequency. If the application circuit requires accuracy of the oscillation frequency, it is necessary to set the oscillation frequency in the application circuit. For this, it is necessary to directly contact the manufacturer of the resonator being used.

(2) μPD78058

Main system clock: ceramic resonator (T_A = -40 to +85 °C)

Manufacturer	Product Name	Frequency (MHz)	Recommended Circuit Constant			Oscillator Voltage Range		Remarks
			C1 (pF)	C2 (pF)	R1 (kΩ)	MIN. (V)	MAX. (V)	
Kyocera Corp.	PBRC4.19A	4.19	33	33	0	2.0	6.0	
	PBRC4.19B	4.19	On chip	On chip	0	2.0	6.0	Capacitor on chip
	KBR-4.19MSA	4.19	33	33	0	2.0	6.0	
	KBR-4.19MKS	4.19	On chip	On chip	0	2.0	6.0	Capacitor on chip
	PBRC4.91A	4.91	33	33	0	2.0	6.0	
	PBRC4.91B	4.91	On chip	On chip	0	2.0	6.0	Capacitor on chip
	KBR-4.91MSA	4.91	33	33	0	2.0	6.0	
	KBR-4.91MKS	4.91	On chip	On chip	0	2.0	6.0	Capacitor on chip

Caution The oscillation circuit constants and oscillation voltage range indicate conditions for stable oscillation. However, they do not guarantee accuracy of the oscillation frequency. If the application circuit requires accuracy of the oscillation frequency, it is necessary to set the oscillation frequency in the application circuit. For this, it is necessary to directly contact the manufacturer of the resonator being used.

Capacitance (T_A = 25°C, V_{DD} = V_{SS} = 0 V)

Parameter	Symbol	Test Conditions		MIN.	TYP.	MAX.	Unit
Input capacitance	C _{IN}	f = 1 MHz Measured pins returned to 0 V.				15	pF
Input/output capacitance	C _{IO}	f = 1 MHz Measured pins returned to 0 V.	P01 to P06, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P72, P120 to P127, P130, P131			15	pF
			P60 to P63			20	pF

Remark The characteristics of the dual-function pins are the same as those of the port pins unless otherwise specified.

DC Characteristics (T_A = -40 to +85 °C, V_{DD} = 2.0 to 6.0 V)

Parameter	Symbol	Test Conditions	MIN.	TYP	MAX.	Unit
Input voltage, high	V _{IH1}	P10 to P17, P21, P23, P30 to P32, P35 to P37, P40 to P47, P50 to P57, P64 to P67, P71, P120 to P127, P130, P131	V _{DD} = 2.7 to 6.0 V	0.7 V _{DD}	V _{DD}	V
				0.8 V _{DD}	V _{DD}	V
	V _{IH2}	P00 to P06, P20, P22, P24 to P27, P33, P34, P70, P72, RESET	V _{DD} = 2.7 to 6.0 V	0.8 V _{DD}	V _{DD}	V
				0.85 V _{DD}	V _{DD}	V
	V _{IH3}	P60 to P63 (N-ch open-drain)	V _{DD} = 2.7 to 6.0 V	0.7 V _{DD}	15	V
				0.8 V _{DD}	15	V
	V _{IH4}	X1, X2	V _{DD} = 2.7 to 6.0 V	V _{DD} -0.5	V _{DD}	V
				V _{DD} -0.2	V _{DD}	V
	V _{IH5}	XT1/P07, XT2	4.5 V ≤ V _{DD} ≤ 6.0 V	0.8 V _{DD}	V _{DD}	V
			2.7 V ≤ V _{DD} < 4.5 V	0.9 V _{DD}	V _{DD}	V
2.0 V ≤ V _{DD} < 2.7 V ^{Note}			0.9 V _{DD}	V _{DD}	V	
Input voltage, low	V _{IL1}	P10 to P17, P21, P23, P30 to P32, P35 to P37, P40 to P47, P50 to P57, P64 to P67, P71, P120 to P127, P130, P131	V _{DD} = 2.7 to 6.0 V	0	0.3 V _{DD}	V
				0	0.2 V _{DD}	V
	V _{IL2}	P00 to P06, P20, P22, P24 to P27, P33, P34, P70, P72, RESET	V _{DD} = 2.7 to 6.0 V	0	0.2 V _{DD}	V
				0	0.15 V _{DD}	V
	V _{IL3}	P60 to P63	4.5 V ≤ V _{DD} ≤ 6.0 V	0	0.3 V _{DD}	V
			2.7 V ≤ V _{DD} < 4.5 V	0	0.2 V _{DD}	V
				0	0.1 V _{DD}	V
	V _{IL4}	X1, X2	V _{DD} = 2.7 to 6.0 V	0	0.4	V
				0	0.2	V
	V _{IL5}	XT1/P07, XT2	4.5 V ≤ V _{DD} ≤ 6.0 V	0	0.2 V _{DD}	V
2.7 V ≤ V _{DD} < 4.5 V			0	0.1 V _{DD}	V	
2.0 V ≤ V _{DD} < 2.7 V ^{Note}			0	0.1 V _{DD}	V	
Output voltage, high	V _{OH}	V _{DD} = 4.5 to 6.0 V, I _{OH} = -1 mA	V _{DD} -1.0		V	
		I _{OH} = -100 μA	V _{DD} -0.5		V	
Output voltage, low	V _{OL1}	P50 to P57, P60 to P63	V _{DD} = 4.5 to 6.0 V, I _{OL} = 15 mA	0.4	2.0	V
		P01 to P06, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P64 to P67, P70 to P72, P120 to P127, P130, P131	V _{DD} = 4.5 to 6.0 V, I _{OL} = 1.6 mA		0.4	V
	V _{OL2}	SB0, SB1, SCK0	V _{DD} = 4.5 to 6.0 V, open-drain, pulled-up (R = 1 KΩ)		0.2 V _{DD}	V
	V _{OL3}	I _{OL} = 400 μA			0.5	V

Note For use as P07, use an inverter to input the reverse phase of P07 to the XT2 pin.

Remark The characteristics of a dual-function pin and a port pin are the same unless specified otherwise.

DC Characteristics (T_A = -40 to +85 °C, V_{DD} = 2.7 to 6.0 V)

Parameter	Symbol	Test Conditions		MIN.	TYP.	MAX.	Unit
Input leakage current, high	I _{IHH1}	V _{IN} = V _{DD}	P00 to P06, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P72, P120 to P127, P130, P131, <u>RESET</u>			3	μA
	I _{IHH2}		X1, X2, XT1/P07, XT2			20	μA
	I _{IHH3}	V _{IN} = 1.5 V	P60 to P63			80	μA
Input leakage current, low	I _{IIL1}	V _{IN} = 0 V	P00 to P06, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P72, P120 to P127, P130, P131, <u>RESET</u>			-3	μA
	I _{IIL2}		X1, X2, XT1/P07, XT2			-20	μA
	I _{IIL3}	P60 to P63			-3	Note 1	μA
Output leakage current, high	I _{IOLH}	V _{OUT} = V _{DD}				3	μA
Output leakage current, low	I _{IOLL}	V _{OUT} = 0 V				-3	μA
Mask option pull-up resistor	R ₁	V _{IN} = 0 V, P60 to P63		20	40	90	kΩ
Software pull-up resistor ^{Note 2}	R ₂	V _{IN} = 0 V, P01 to P06, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P72, P120 to P127, P130, P131	4.5 V ≤ V _{DD} ≤ 6.0 V	15	40	90	kΩ
			2.7 V ≤ V _{DD} < 4.5 V	20		500	kΩ

Notes 1. For P60 to P63 without on-chip pull-up resistor (specifiable by mask option), a low-level input leakage current of -200 μA (MAX.) flows only during the 1.5 clocks (no wait) after an instruction has been executed to read out port 6 (P6) or port mode register 6 (PM6). Outside the period of 1.5 clocks following executing a read-out instruction, the current is -3 μA (MAX.).

2. A software pull-up resistor can be used only in the range of V_{DD} = 2.7 to 6.0 V.

Remark The characteristics of a dual-function pin and a port pin are the same unless specified otherwise.

DC Characteristics (T_A = -40 to +85 °C, V_{DD} = 2.0 to 6.0 V)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit	
Power supply current <small>Note 5</small>	I _{DD1}	5.0 MHz Crystal oscillation operating mode (f _{xx} = 2.5 MHz) <small>Note 3</small>	V _{DD} = 5.0 V ± 10 % <small>Note 1</small>		4	12	mA
			V _{DD} = 3.0 V ± 10 % <small>Note 2</small>		0.6	1.8	mA
			V _{DD} = 2.2 V ± 10 % <small>Note 2</small>		0.35	1.05	mA
		5.0 MHz Crystal oscillation operating mode (f _{xx} = 5.0 MHz) <small>Note 4</small>	V _{DD} = 5.0 V ± 10 % <small>Note 1</small>		6.5	19.5	mA
			V _{DD} = 3.0 V ± 10 % <small>Note 2</small>		0.8	2.4	mA
			V _{DD} = 2.2 V ± 10 %				
	I _{DD2}	5.0 MHz Crystal oscillation HALT mode (f _{xx} = 2.5 MHz) <small>Note 3</small>	V _{DD} = 5.0 V ± 10 %		1.4	4.2	mA
			V _{DD} = 3.0 V ± 10 %		0.5	1.5	mA
		5.0 MHz Crystal oscillation HALT mode (f _{xx} = 5.0 MHz) <small>Note 4</small>	V _{DD} = 2.2 V ± 10 %		280	840	μA
			V _{DD} = 5.0 V ± 10 %		1.6	4.8	mA
	I _{DD3}	32.768 kHz Crystal oscillation operating mode <small>Note 6</small>	V _{DD} = 5.0 V ± 10 %		60	120	μA
			V _{DD} = 3.0 V ± 10 %		32	64	μA
V _{DD} = 2.2 V ± 10 %				24	48	μA	
I _{DD4}	32.768 kHz Crystal oscillation HALT mode <small>Note 6</small>	V _{DD} = 5.0 V ± 10 %		25	55	μA	
		V _{DD} = 3.0 V ± 10 %		5	15	μA	
		V _{DD} = 2.2 V ± 10 %		2.5	12.5	μA	
★ I _{DD5}	XT1 = V _{DD} STOP mode When feedback resistor is used	V _{DD} = 5.0 V ± 10 %		1	30	μA	
		V _{DD} = 3.0 V ± 10 %		0.5	10	μA	
		V _{DD} = 2.2 V ± 10 %		0.3	10	μA	
★ I _{DD6}	XT1 = V _{DD} STOP mode When feedback resistor is unused	V _{DD} = 5.0 V ± 10 %		0.1	30	μA	
		V _{DD} = 3.0 V ± 10 %		0.05	10	μA	
		V _{DD} = 2.2 V ± 10 %		0.05	10	μA	

- Notes**
- Operating in high-speed mode (when set the processor clock control register (PCC) to 00H).
 - Operating in low-speed mode (when set the PCC to 04H).
 - Operation with f_{xx} = f_x/2 (when oscillation mode selection register (OSMS) is set to 00H)
 - Operation with f_{xx} = f_x (when OSMS is set to 01H)
 - This current flows in the V_{DD} and AV_{DD} pins.
However, a current flowing in the A/D converter, D/A converter, and on-chip pull-up resistor are not included.
 - When the main system clock is halted

Remark f_{xx}: Main system clock frequency (f_x or f_x/2)
f_x: Main system clock oscillator frequency

AC Characteristics

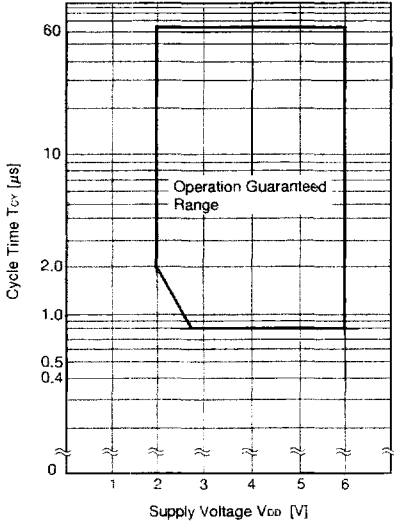
(1) Basic operation (T_A = -40 to +85 °C, V_{DD} = 2.0 to 6.0 V)

Parameter	Symbol	Test Conditions		MIN.	TYP.	MAX.	Unit
Cycle time (Min. instruction execution time)	T _{CY}	Operating on main system clock	f _{xx} = f _x /2 ^{Note 1}	V _{DD} = 2.7 to 6.0 V	0.8	64	μS
					2.2	64	μS
			f _{xx} = f _x ^{Note 2}	4.5 V ≤ V _{DD} ≤ 6.0 V	0.4	32	μS
				2.7 V ≤ V _{DD} < 4.5 V	0.8	32	μS
		Operating on sub system clock		40	122	125	μS
TI00, TI01, TI1, TI2 input frequency	f _{TI}	V _{DD} = 4.5 to 6.0 V		0		4	MHz
				0		275	KHz
TI00 input high/ low level width	t _{TIH} , t _{TIL}			8/f _{san} ^{Note 3}			μS
TI01, TI1, TI2 input high/ low-level width	t _{TIH} , t _{TIL}	V _{DD} = 4.5 to 6.0 V		100			ns
				1.8			μS
Interrupt input high/low-level width	t _{INTH} , t _{INTL}	INTP0		8/f _{san} ^{Note 3}			μS
		INTP1 to INTP6, KR0 to KR7	V _{DD} = 2.7 to 6.0 V	10			μS
				20			μS
RESET low level width	t _{RESL}	V _{DD} = 2.7 to 6.0 V		10			μS
				20			μS

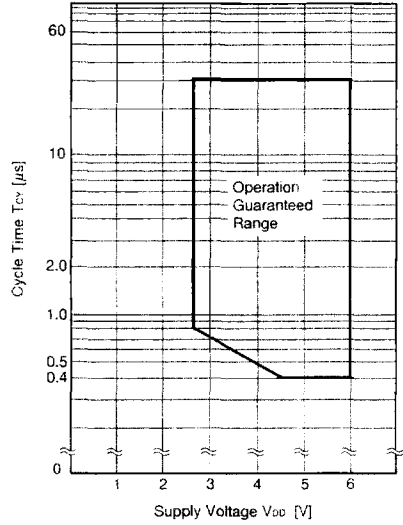
- Notes**
1. When oscillation mode selection register (OSMS) is set to 00H
 2. When OSMS is set to 01H
 3. In combination with bits 0 (SCS0) and 1 (SCS1) of sampling clock select register (SCS), selection of f_{san} is possible between f_{xx}/2^N, f_{xx}/32, f_{xx}/64 and f_{xx}/128 (when N = 0 to 4).

Remark f_{xx}: Main system clock frequency (f_x or f_x/2)
 f_x : Main system clock oscillation frequency

T_{CY} vs V_{DD} (At $f_{xx} = f_x/2$ main system clock operation)



T_{CY} vs V_{DD} (At $f_{xx} = f_x$ main system clock operation)



(2) Read/write operation

(a) When MCS = 1, PCC2 to PCC0 = 000B ($T_A = -40$ to $+85$ °C, $V_{DD} = 4.5$ to 6.0 V)

Parameter	Symbol	Test Conditions	MIN.	MAX.	Unit
ASTB high-level width	t_{ASTH}		$0.85t_{CY} - 50$		ns
Address setup time	t_{ADS}		$0.85t_{CY} - 50$		ns
Address hold time	t_{ADH}		50		ns
Data input time from address	t_{ADD1}			$(2.85+2n)t_{CY}-80$	ns
	t_{ADD2}			$(4+2n)t_{CY}-100$	ns
Data input time from $\overline{RD}\downarrow$	t_{RDD1}			$(2+2n)t_{CY}-100$	ns
	t_{RDD2}			$(2.85+2n)t_{CY}-100$	ns
Read data hold time	t_{RDH}		0		ns
\overline{RD} low-level width	t_{RDL1}		$(2+2n)t_{CY}-60$		ns
	t_{RDL2}		$(2.85+2n)t_{CY}-60$		ns
$\overline{WAIT}\downarrow$ input time from $\overline{RD}\downarrow$	t_{RDWT1}			$0.85t_{CY}-50$	ns
	t_{RDWT2}			$2t_{CY}-60$	ns
$\overline{WAIT}\downarrow$ input time from $\overline{WR}\downarrow$	t_{WRWT}			$2t_{CY}-60$	ns
\overline{WAIT} low-level width	t_{WTL}		$(1.15+2n)t_{CY}$	$(2+2n)t_{CY}$	ns
Write data setup time	t_{WDS}		$(2.85+2n)t_{CY}-100$		ns
Write data hold time	t_{WDH}		20		ns
\overline{WR} low-level width	t_{WRL}		$(2.85+2n)t_{CY}-60$		ns
$\overline{RD}\downarrow$ delay time from $\overline{ASTB}\downarrow$	t_{ASTRD}		25		ns
$\overline{WR}\downarrow$ delay time from $\overline{ASTB}\downarrow$	t_{ASTWR}		$0.85t_{CY} + 20$		ns
ASTB \uparrow delay time from $\overline{RD}\uparrow$ in external fetch	t_{RDAST}		$0.85t_{CY} - 10$	$1.15t_{CY} + 20$	ns
Address hold time from $\overline{RD}\uparrow$ in external fetch	t_{RDADH}		$0.85t_{CY} - 50$	$1.15t_{CY} + 50$	ns
Write data output time from $\overline{RD}\uparrow$	t_{RDWD}		40		ns
Write data output time from $\overline{WR}\downarrow$	t_{WRWD}		0	50	ns
Address hold time from $\overline{WR}\uparrow$	t_{WRADH}		$0.85t_{CY}$	$1.15t_{CY} + 40$	ns
$\overline{RD}\uparrow$ delay time from $\overline{WAIT}\uparrow$	t_{WTRD}		$1.15t_{CY} + 40$	$3.15t_{CY} + 40$	ns
$\overline{WR}\uparrow$ delay time from $\overline{WAIT}\uparrow$	t_{WTRW}		$1.15t_{CY} + 30$	$3.15t_{CY} + 30$	ns

- Remarks**
1. MCS: Oscillation mode selection register (OSMS) bit 0
 2. PCC2 to PCC0: Processor clock control register (PCC) bit 2 to bit 0
 3. $t_{CY} = T_{CY}/4$
 4. n indicates number of waits.

(b) When except MCS = 1, PCC2 to PCC0 = 000B (T_A = -40 to +85 °C, V_{DD} = 2.0 to 6.0 V)

Parameter	Symbol	Test Conditions	MIN.	MAX.	Unit
ASTB high-level width	t _{ASTH}	V _{DD} = 2.7 to 6.0 V	t _{cy} - 80		ns
			t _{cy} - 150		ns
Address setup time	t _{ACS}	V _{DD} = 2.7 to 6.0 V	t _{cy} - 80		ns
			t _{cy} - 150		ns
Address hold time	t _{ADH}	V _{DD} = 2.7 to 6.0 V	0.4t _{cy} - 10		ns
			0.37t _{cy} - 40		ns
Data input time from address	t _{ADD1}	V _{DD} = 2.7 to 6.0 V		(3+2n)t _{cy} -160	ns
				(3+2n)t _{cy} -320	ns
	t _{ADD2}	V _{DD} = 2.7 to 6.0 V		(4+2n)t _{cy} -200	ns
				(4+2n)t _{cy} -300	ns
Data input time from RD↓	t _{RDD1}	V _{DD} = 2.7 to 6.0 V		(1.4+2n)t _{cy} -70	ns
				(1.37+2n)t _{cy} -120	ns
	t _{RDD2}	V _{DD} = 2.7 to 6.0 V		(2.4+2n)t _{cy} -70	ns
				(2.37+2n)t _{cy} -120	ns
t _{RDH}		0		ns	
RD low-level width	t _{RDL1}	V _{DD} = 2.7 to 6.0 V	(1.4+2n)t _{cy} -20		ns
			(1.37+2n)t _{cy} -20		ns
	t _{RDL2}	V _{DD} = 2.7 to 6.0 V	(2.4+2n)t _{cy} -20		ns
			(2.37+2n)t _{cy} -20		ns
WAIT↓ input time from RD↓	t _{RDWT1}	V _{DD} = 2.7 to 6.0 V		t _{cy} -100	ns
				t _{cy} -200	ns
	t _{RDWT2}	V _{DD} = 2.7 to 6.0 V		2t _{cy} -100	ns
				2t _{cy} -200	ns
t _{WRWT}	V _{DD} = 2.7 to 6.0 V		2t _{cy} -100	ns	
			2t _{cy} -200	ns	
t _{WTL}		(1+2n)t _{cy}	(2+2n)t _{cy}	ns	
Write data setup time	t _{WDS}	V _{DD} = 2.7 to 6.0 V	(2.4+2n)t _{cy} -60		ns
			(2.37+2n)t _{cy} -100		ns
t _{WDH}		20		ns	
WR low-level width	t _{WRL}	V _{DD} = 2.7 to 6.0 V	(2.4+2n)t _{cy} -20		ns
			(2.37+2n)t _{cy} -20		ns
RD↓ delay time from ASTB↓	t _{ASTRD}	V _{DD} = 2.7 to 6.0 V	0.4t _{cy} - 30		ns
			0.37t _{cy} - 50		ns
WR↓ delay time from ASTB↓	t _{ASTWR}	V _{DD} = 2.7 to 6.0 V	1.4t _{cy} - 30		ns
			1.37t _{cy} - 50		ns

- Remarks**
1. MCS: Oscillation mode selection register (OSMS) bit 0
 2. PCC2 to PCC0: Processor clock control register (PCC) bit 2 to bit 0
 3. t_{cy} = T_{cy}/4
 4. n indicates number of waits.

(b) When except MCS = 1, PCC2 to PCC0 = 000B ($T_A = -40$ to $+85$ °C, $V_{DD} = 2.0$ to 6.0 V)

Parameter	Symbol	Test Conditions	MIN.	MAX.	Unit
ASTB \uparrow delay time from $\overline{RD}\uparrow$ in external fetch	t _{ROAST}		t _{cy} - 10	t _{cy} + 20	ns
Address hold time from $\overline{RD}\uparrow$ in external fetch	t _{ROADH}		t _{cy} - 50	t _{cy} + 50	ns
Write data output time from $\overline{RD}\uparrow$	t _{ROWD}	$V_{DD} = 2.7$ to 6.0 V	0.4t _{cy} - 20		ns
			0.37t _{cy} - 40		ns
Write data output time from $\overline{WR}\downarrow$	t _{WRWD}	$V_{DD} = 2.7$ to 6.0 V	0	60	ns
			0	120	ns
Address hold time from $\overline{WR}\uparrow$	t _{WRADH}	$V_{DD} = 2.7$ to 6.0 V	t _{cy}	t _{cy} + 60	ns
			t _{cy}	t _{cy} + 120	ns
$\overline{RD}\uparrow$ delay time from $\overline{WAIT}\uparrow$	t _{WRD}	$V_{DD} = 2.7$ to 6.0 V	0.6t _{cy} + 180	2.6t _{cy} + 180	ns
			0.63t _{cy} + 350	2.63t _{cy} + 350	ns
$\overline{WR}\uparrow$ delay time from $\overline{WAIT}\uparrow$	t _{WTR}	$V_{DD} = 2.7$ to 6.0 V	0.6t _{cy} + 120	2.6t _{cy} + 120	ns
			0.63t _{cy} + 240	2.63t _{cy} + 240	ns

- Remarks**
1. MCS: Oscillation mode selection register (OSMS) bit 0
 2. PCC2 to PCC0: Processor clock control register (PCC) bit 2 to bit 0
 3. t_{cy} = T_{cy}/4
 4. n indicates number of waits.

(3) Serial interface ($T_A = -40$ to $+85$ °C, $V_{DD} = 2.0$ to 6.0 V)

(a) Serial interface channel 0

(i) 3-wire serial I/O mode ($\overline{SCK0}$... Internal clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
$\overline{SCK0}$ cycle time	t_{CY1}	$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$	800			ns
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$	1600			ns
			3200			ns
$\overline{SCK0}$ high/low-level width	t_{KH1}, t_{KL1}	$V_{DD} = 4.5$ to 6.0 V	$t_{CY1}/2-50$			ns
			$t_{CY1}/2-100$			ns
SIO setup time (to $\overline{SCK0}\uparrow$)	t_{SIK1}	$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$	100			ns
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$	150			ns
			300			ns
SIO hold time (from $\overline{SCK0}\downarrow$)	t_{SH1}		400			ns
SO0 output delay time from $\overline{SCK0}\downarrow$	t_{KS01}	$C = 100\text{ pF}$ <i>Note</i>			300	ns

Note C is the load capacitance of SO0 output line.

(ii) 3-wire serial I/O mode ($\overline{SCK0}$... External clock input)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
$\overline{SCK0}$ cycle time	t_{CY2}	$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$	800			ns
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$	1600			ns
			3200			ns
$\overline{SCK0}$ high/low-level width	t_{KH2}, t_{KL2}	$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$	400			ns
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$	800			ns
			1600			ns
SIO setup time (to $\overline{SCK0}\uparrow$)	t_{SIK2}		100			ns
SIO hold time (from $\overline{SCK0}\downarrow$)	t_{SH2}		400			ns
SO0 output delay time from $\overline{SCK0}\downarrow$	t_{KS02}	$C = 100\text{ pF}$ <i>Note</i>			300	ns
$\overline{SCK0}$ rise, fall time	t_{R2}, t_{F2}	When using external device expansion function			150	ns
		When not using external device expansion function			1000	ns

Note C is the load capacitance of SO0 output line.

(iii) SBI mode ($\overline{\text{SCK0}}$... Internal clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
$\overline{\text{SCK0}}$ cycle time	t_{KCY3}	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	800			ns
			3200			ns
$\overline{\text{SCK0}}$ high/low-level width	$t_{\text{KH3}}, t_{\text{KL3}}$	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	$t_{\text{KCY3}}/2-50$			ns
			$t_{\text{KCY3}}/2-150$			ns
SB0, SB1 setup time (to $\overline{\text{SCK0}}\uparrow$)	t_{SIK3}	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	100			ns
			300			ns
SB0, SB1 hold time (from $\overline{\text{SCK0}}\uparrow$)	t_{KH3}		$t_{\text{KCY3}}/2$			ns
SB0, SB1 output delay time from $\overline{\text{SCK0}}\downarrow$	t_{KSO3}	R = 1 kΩ , C = 100 pF Note	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	0	250	ns
				0	1000	ns
SB0, SB1↓ from $\overline{\text{SCK0}}\uparrow$	t_{KSB}		t_{KCY3}			ns
$\overline{\text{SCK0}}\downarrow$ from SB0, SB1↓	t_{SBK}		t_{KCY3}			ns
SB0, SB1 high-level width	t_{SBH}		t_{KCY3}			ns
SB0, SB1 low-level width	t_{SBL}		t_{KCY3}			ns

Note R and C are the load resistors and load capacitance of the $\overline{\text{SCK0}}$, SB0 and SB1 output line.

(iv) SBI mode ($\overline{\text{SCK0}}$... External clock input)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
$\overline{\text{SCK0}}$ cycle time	t_{KCY4}	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	800			ns
			3200			ns
$\overline{\text{SCK0}}$ high/low-level width	$t_{\text{KH4}}, t_{\text{KL4}}$	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	400			ns
			1600			ns
SB0, SB1 setup time (to $\overline{\text{SCK0}}\uparrow$)	t_{SIK4}	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	100			ns
			300			ns
SB0, SB1 hold time (from $\overline{\text{SCK0}}\uparrow$)	t_{KH4}		$t_{\text{KCY4}}/2$			ns
SB0, SB1 output delay time from $\overline{\text{SCK0}}\downarrow$	t_{KSO4}	R = 1 kΩ , C = 100 pF Note	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	0	300	ns
				0	1000	ns
SB0, SB1↓ from $\overline{\text{SCK0}}\uparrow$	t_{KSB}		t_{KCY4}			ns
$\overline{\text{SCK0}}\downarrow$ from SB0, SB1↓	t_{SBK}		t_{KCY4}			ns
SB0, SB1 high-level width	t_{SBH}		t_{KCY4}			ns
SB0, SB1 low-level width	t_{SBL}		t_{KCY4}			ns
$\overline{\text{SCK0}}$ rise, fall time	$t_{\text{r4}}, t_{\text{f4}}$	When using external device expansion function			160	ns
			When not using external device expansion function			1000

Note R and C are the load resistors and load capacitance of the SB0 and SB1 output line.

(v) 2-wire serial I/O mode (SCK0... Internal clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit	
SCK0 cycle time	t _{CVS}	R = 1 kΩ, C = 100 pF Note	V _{DD} = 2.7 to 6.0 V	1600		ns	
				3200		ns	
SCK0 high-level width	t _{KHS}		V _{DD} = 2.7 to 6.0 V	t _{CVS} /2-160		ns	
				t _{CVS} /2-190		ns	
SCK0 low-level width	t _{KLS}		V _{DD} = 4.5 to 6.0 V	t _{CVS} /2-50		ns	
				t _{CVS} /2-100		ns	
SB0, SB1 setup time (to SCK0↑)	t _{SKS}		4.5 V ≤ V _{DD} ≤ 6.0 V	300		ns	
				2.7 V ≤ V _{DD} < 4.5 V	350		ns
				400		ns	
SB0, SB1 hold time (from SCK0↑)	t _{SHS}		600		ns		
SB0, SB1 output delay time from SCK0↓	t _{KSOS}		0		300	ns	

Note R and C are the load resistors and load capacitance of the SCK0, SB0 and SB1 output line.

(vi) 2-wire serial I/O mode (SCK0... Internal clock input)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit	
SCK0 cycle time	t _{CVS}	V _{DD} = 2.7 to 6.0 V	1600			ns	
			3200			ns	
SCK0 high-level width	t _{KHS}	V _{DD} = 2.7 to 6.0 V	650			ns	
			1300			ns	
SCK0 low-level width	t _{KLS}	V _{DD} = 2.7 to 6.0 V	800			ns	
			1600			ns	
SB0, SB1 setup time (to SCK0↑)	t _{SKS}		100			ns	
SB0, SB1 hold time (from SCK0↑)	t _{SHS}		t _{CVS} /2			ns	
SB0, SB1 output delay time from SCK0↓	t _{KSOS}	R = 1 kΩ, C = 100 pF Note	V _{DD} = 4.5 to 6.0 V	0		300	ns
				0		500	ns
SCK0 rise, fall time	t _{RS} , t _{FS}	When using external device expansion function			160	ns	
		When not using external device expansion function			1000	ns	

Note R and C are the load resistors and load capacitance of the SCK0, SB0 and SB1 output line.

(b) Serial interface channel 1

(i) 3-wire serial I/O mode ($\overline{\text{SCK1}}$...Internal clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
$\overline{\text{SCK1}}$ cycle time	t_{CY7}	$4.5 \text{ V} \leq V_{\text{DD}} \leq 6.0 \text{ V}$	800			ns
		$2.7 \text{ V} \leq V_{\text{DD}} < 4.5 \text{ V}$	1600			ns
			3200			ns
$\overline{\text{SCK1}}$ high/low-level width	$t_{\text{KH7}}, t_{\text{KL7}}$	$V_{\text{DD}} = 4.5 \text{ to } 6.0 \text{ V}$	$t_{\text{CY7}}/2-50$			ns
			$t_{\text{CY7}}/2-100$			ns
SI1 setup time (to $\overline{\text{SCK1}}\uparrow$)	t_{SIK7}	$4.5 \text{ V} \leq V_{\text{DD}} \leq 6.0 \text{ V}$	100			ns
		$2.7 \text{ V} \leq V_{\text{DD}} < 4.5 \text{ V}$	150			ns
			300			ns
SI1 hold time (from $\overline{\text{SCK1}}\uparrow$)	t_{SH7}		400			ns
SO1 output delay time from $\overline{\text{SCK1}}\downarrow$	t_{SO7}	$C = 100 \text{ pF}$ ^{Note}			300	ns

Note C is the load capacitance of the SO1 output line.

(ii) 3-wire serial I/O mode ($\overline{\text{SCK1}}$...External clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
$\overline{\text{SCK1}}$ cycle time	t_{CY8}	$4.5 \text{ V} \leq V_{\text{DD}} \leq 6.0 \text{ V}$	800			ns
		$2.7 \text{ V} \leq V_{\text{DD}} < 4.5 \text{ V}$	1600			ns
			3200			ns
$\overline{\text{SCK1}}$ high/low-level width	$t_{\text{KH8}}, t_{\text{KL8}}$	$4.5 \text{ V} \leq V_{\text{DD}} \leq 6.0 \text{ V}$	400			ns
		$2.7 \text{ V} \leq V_{\text{DD}} < 4.5 \text{ V}$	800			ns
			1600			ns
SI1 setup time (to $\overline{\text{SCK1}}\uparrow$)	t_{SIK8}		100			ns
SI1 hold time (from $\overline{\text{SCK1}}\uparrow$)	t_{SH8}		400			ns
SO1 output delay time from $\overline{\text{SCK1}}\downarrow$	t_{SO8}	$C = 100 \text{ pF}$ ^{Note}			300	ns
$\overline{\text{SCK1}}$ rise, fall time	$t_{\text{rs}}, t_{\text{fs}}$	When using external device expansion function			160	ns
		When not using external device expansion function			1000	ns

Note C is the load capacitance of the SO output line.

(iii) 3-wire serial I/O mode with automatic transmit/receive function (SCK1...Internal clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
SCK1 cycle time	t _{KCV9}	4.5 V ≤ V _{DD} ≤ 6.0 V	800			ns
		2.7 V ≤ V _{DD} < 4.5 V	1600			ns
			3200			ns
SCK1 high/low-level width	t _{KH9} , t _{KL9}	V _{DD} = 4.5 to 6.0 V	t _{KCV9} /2-50			ns
			t _{KCV9} /2-100			ns
SI1 setup time (to SCK1↑)	t _{SK9}	4.5 V ≤ V _{DD} ≤ 6.0 V	100			ns
		2.7 V ≤ V _{DD} < 4.5 V	150			ns
			300			ns
SI1 hold time (from SCK1↑)	t _{SH9}		400			ns
SO1 output delay time from SCK1↓	t _{KSO9}	C = 100 pF ^{Note}			300	ns
STB↑ from SCK1↑	t _{SB9}		t _{KCV9} /2-100		t _{KCV9} /2+100	ns
Strobe signal high-level width	t _{SW}	V _{DD} = 2.7 to 6.0V	t _{KCV9} -30		t _{KCV9} +30	ns
			t _{KCV9} -60		t _{KCV9} +60	ns
Busy signal setup time (to busy signal detection timing)	t _{BS}		100			ns
Busy signal hold time (from busy signal detection timing)	t _{BH}	4.5 V ≤ V _{DD} ≤ 6.0 V	100			ns
		2.7 V ≤ V _{DD} < 4.5 V	150			ns
			200			ns
SCK1↓ from busy inactive	t _{SPS}				2t _{KCV9}	ns

Note C is the load capacitance of the SO1 output line.

(iv) 3-wire serial I/O mode with automatic transmit/receive function (SCK1...External clock input)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
SCK1 cycle time	t _{KCV10}	4.5 V ≤ V _{DD} ≤ 6.0 V	800			ns
		2.7 V ≤ V _{DD} < 4.5 V	1600			ns
			3200			ns
SCK1 high/low-level width	t _{KH10} , t _{KL10}	4.5 V ≤ V _{DD} ≤ 6.0 V	400			ns
		2.7 V ≤ V _{DD} < 4.5 V	800			ns
			1600			ns
SI1 setup time (to SCK1↑)	t _{SK10}		100			ns
SI1 hold time (from SCK1↑)	t _{SH10}		400			ns
SO1 output delay time from SCK1↓	t _{KSO10}	C = 100 pF ^{Note}			300	ns
SCK1 rise, fall time	t _{R10} , t _{F10}	When using external device expansion function			160	ns
		When not using external device expansion function			1000	ns

Note C is the load capacitance of the SO1 output line.

(c) Serial interface channel 2

(i) 3-wire serial I/O mode (SCK2...Internal clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
SCK2 cycle time	t _{KCY11}	4.5 V ≤ V _{DD} ≤ 6.0 V	800			ns
		2.7 V ≤ V _{DD} < 4.5 V	1600			ns
			3200			ns
SCK2 high/low-level width	t _{KH11} , t _{KL11}	V _{DD} = 4.5 to 6.0 V	t _{KCY11} /2-50			ns
			t _{KCY11} /2-100			ns
SI2 setup time (to <u>SCK2</u> ↑)	t _{SK11}	4.5 V ≤ V _{DD} ≤ 6.0 V	100			ns
		2.7 V ≤ V _{DD} < 4.5 V	150			ns
			300			ns
SI2 hold time (from <u>SCK2</u> ↑)	t _{KH11}		400			ns
SO2 output delay time from <u>SCK2</u> ↓	t _{KSO11}	C = 100 pF Note			300	ns

Note C is the load capacitance of the SO2 output line.

(ii) 3-wire serial I/O mode with automatic transmit/receive function (SCK2...External clock output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
SCK2 cycle time	t _{KCY12}	4.5 V ≤ V _{DD} ≤ 6.0 V	800			ns
		2.7 V ≤ V _{DD} < 4.5 V	1600			ns
			3200			ns
SCK2 high/low-level width	t _{KH12} , t _{KL12}	4.5 V ≤ V _{DD} ≤ 6.0 V	400			ns
		2.7 V ≤ V _{DD} < 4.5 V	800			ns
			1600			ns
SI2 setup time (to <u>SCK2</u> ↑)	t _{SK12}		100			ns
SI2 hold time (from <u>SCK2</u> ↑)	t _{KH12}		400			ns
SO2 output delay time from <u>SCK2</u> ↓	t _{KSO12}	C = 100 pF Note			300	ns
SCK2 rise, fall time	t _{R12} , t _{F12}	When using external device expansion function			160	ns
		When not using external device expansion function			1000	ns

Note C is the load capacitance of the SO2 output line.

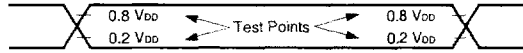
(iii) UART mode (Dedicated baud rate generator output)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate		$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$			78125	bps
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$			39063	bps
					19531	bps

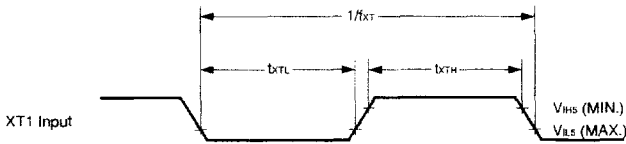
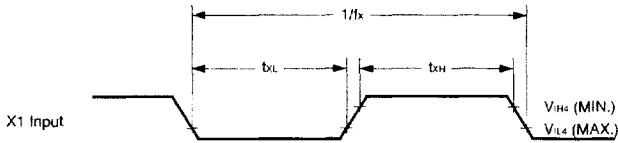
(iv) UART mode (External clock input)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
ASCK cycle time	t_{KCY13}	$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$	800			ns
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$	1600			ns
			3200			ns
ASCK high-/low-level width	t_{KH13} , t_{KL13}	$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$	400			ns
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$	800			ns
			1600			ns
Transfer rate		$4.5\text{ V} \leq V_{DD} \leq 6.0\text{ V}$			39063	bps
		$2.7\text{ V} \leq V_{DD} < 4.5\text{ V}$			19531	bps
					9766	bps
ASCK rise, fall time	t_{r13} , t_{f13}	$V_{DD} = 4.5\text{ to }6.0\text{ V}$, when not using external device expansion function.			1000	ns
					160	ns

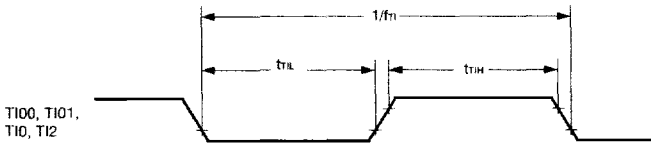
AC Timing Test Point (Excluding X1, XT1 Input)



Clock Timing

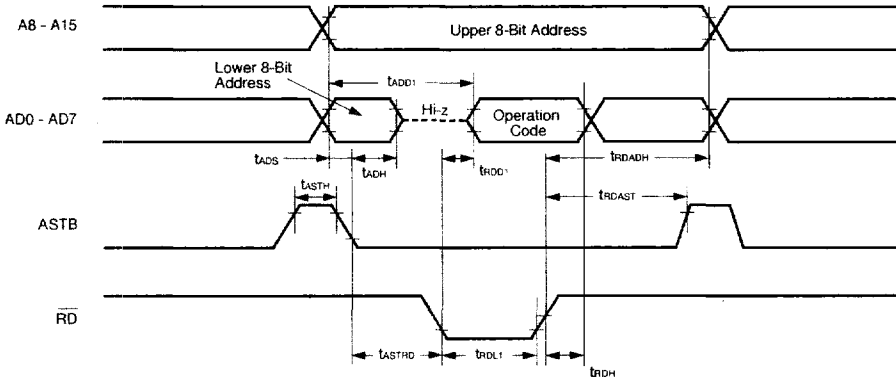


T1 Timing

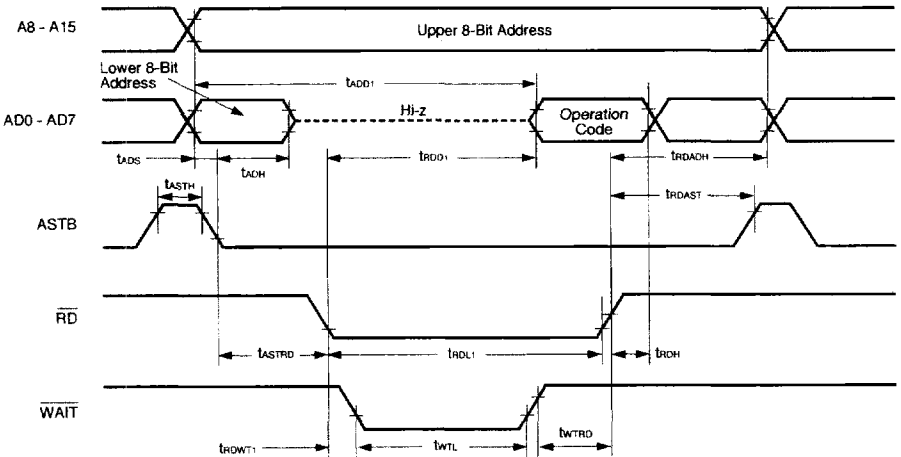


Read/Write Operation

External fetch (no wait) :

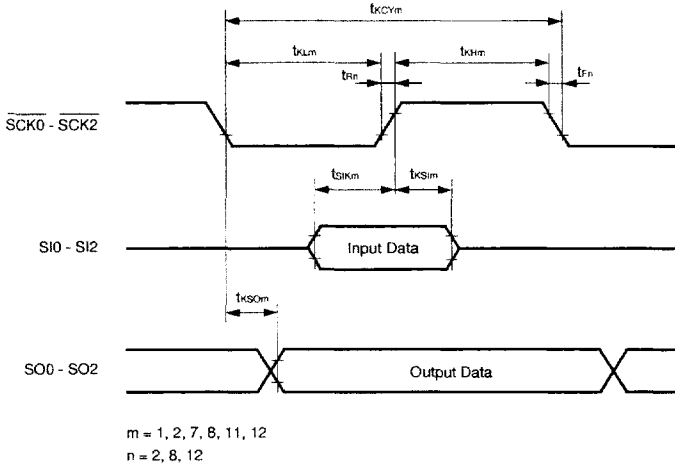


External fetch (wait insertion) :

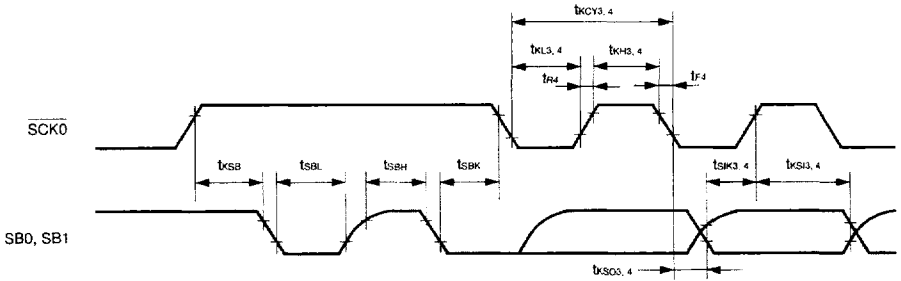


Serial Transfer Timing

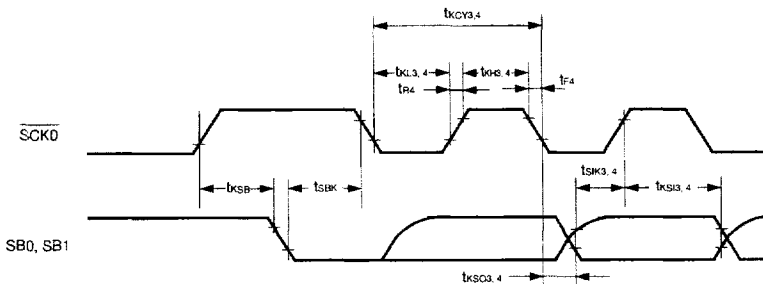
3-wire serial I/O mode :



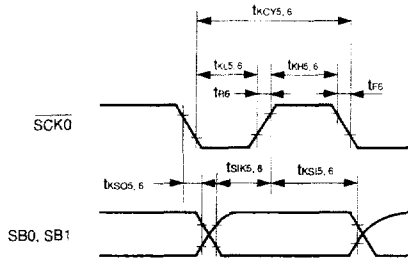
SBI mode (bus release signal transfer) :



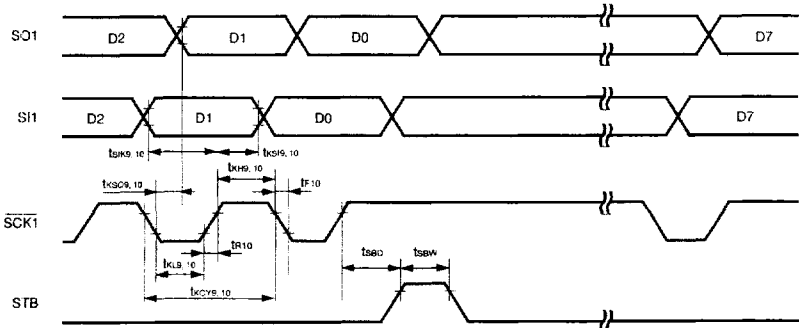
SBI mode (command signal transfer) :



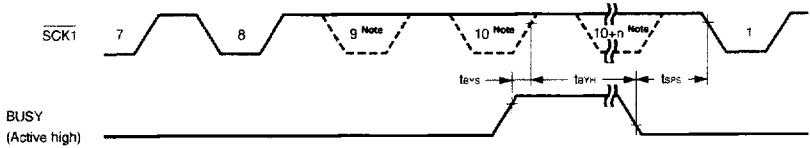
2-wire serial I/O mode :



3-wire serial I/O mode with automatic transmit/receive function :

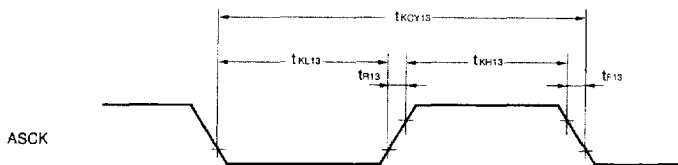


3-wire serial I/O mode with automatic transmit/receive function (busy processing) :



Note The signal is not actually driven low here; it is shown as such to indicate the timing.

UART mode (external clock input) :



A/D Converter Characteristics ($T_A = -40$ to $+85$ °C, $AV_{DD} = V_{DD} = 2.0$ to 6.0 V, $AV_{SS} = V_{SS} = 0$ V)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Resolution			8	8	8	bit
Overall error Note		$2.7\text{ V} \leq AV_{REF0} \leq AV_{DD}$			0.6	%
		$2.0\text{ V} \leq AV_{REF0} < 2.7\text{ V}$			1.4	%
Conversion time	t_{CONV}		19.1		200	μs
Sampling time	t_{SAMP}		12/f _{xx}			μs
Analog input voltage	V_{IAN}		AV_{SS}		AV_{REF0}	V
Reference voltage	AV_{REF0}		2.0		AV_{DC}	V
Resistance between AV_{REF0} and AV_{SS}	R_{AREF0}		4	14		kΩ

Note Overall error excluding quantization error ($\pm 1/2$ LSB). It is indicated as a ratio to the full-scale value.

Remark f_{xx} : Main system clock frequency (f_x or f_x/2)

f_x : Main system clock oscillation frequency

D/A Converter Characteristics ($T_A = -40$ to $+85$ °C, $V_{DD} = 2.0$ to 6.0 V, $AV_{SS} = V_{SS} = 0$ V)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Resolution					8	bit
Overall error		$R = 2M\Omega$ Note 1			1.2	%
		$R = 4M\Omega$ Note 1			0.8	%
		$R = 10M\Omega$ Note 1			0.6	%
Setting time		Note $C = 30pF$ $4.5\text{ V} \leq AV_{REF1} \leq 6.0\text{ V}$			10	μs
		$2.7\text{ V} \leq AV_{REF1} < 4.5\text{ V}$			15	μs
		$2.0\text{ V} \leq AV_{REF1} < 2.7\text{ V}$			20	μs
Output resistance	R_O	DACS0, DACS1 = 65H Note 2		10		kΩ
Analog reference voltage	AV_{REF1}		2.0		V_{CO}	V
AV_{REF1} current	I_{REF1}	Note 2			1.5	mA

Notes 1. R and C denote D/A converter output pin load resistance and load capacitance, respectively.

2. Value for 1 D/A converter channel

Remark DACS0 and DACS1: D/A conversion value setting register 0 and 1

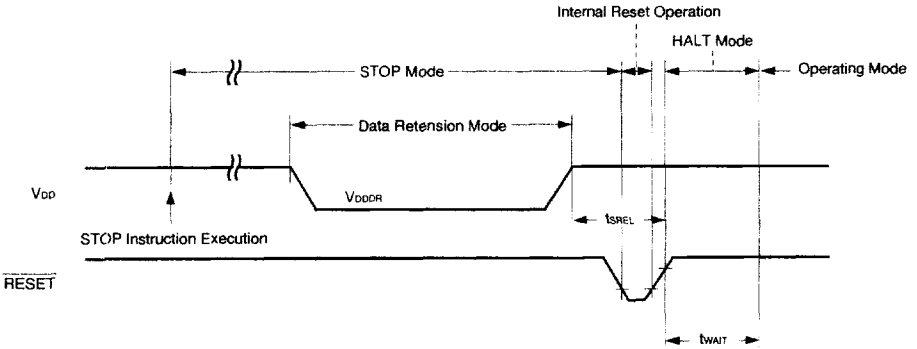
Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics (T_A = -40 to +85°C)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Data retention power supply voltage	V _{DDDR}		1.8		6.0	V
Data retention power supply current	I _{DDDR}	V _{DDDR} = 1.8 V Subsystem clock stop and feed-back resistor disconnected		0.1	10	μA
Release signal set time	t _{SREL}		0			μs
Oscillation stablilation wait time	t _{WAIT}	Release by $\overline{\text{RESET}}$		2 ¹² /f _x		ms
		Release by interrupt		Note		ms

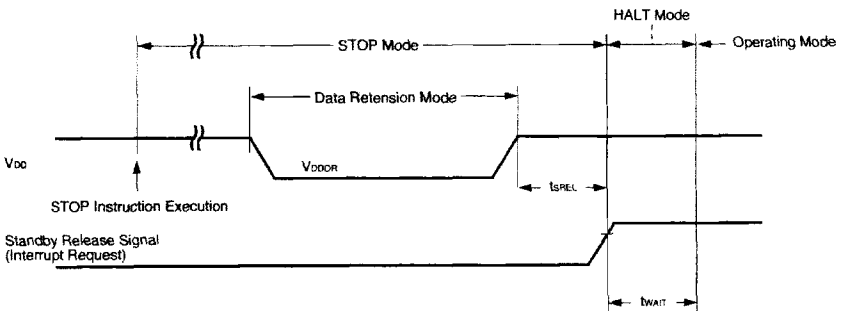
Note In combination with bits 0 to 2 (OSTS0 to OSTs2) of oscillation stabilization time select register (OSTS), selection of 2¹²/f_{xx} and 2¹⁴/f_{xx} to 2¹⁷/f_{xx} is possible.

Remark f_{xx}: Main system clock frequency (f_x or f_x/2)
f_x: Main system clock oscillator frequency

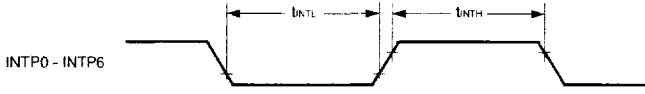
Data Retention Timing (STOP Mode Release by $\overline{\text{RESET}}$)



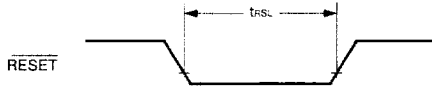
Data Retention Timing (Standby Release Signal: STOP Mode Release by Interrupt Signal)



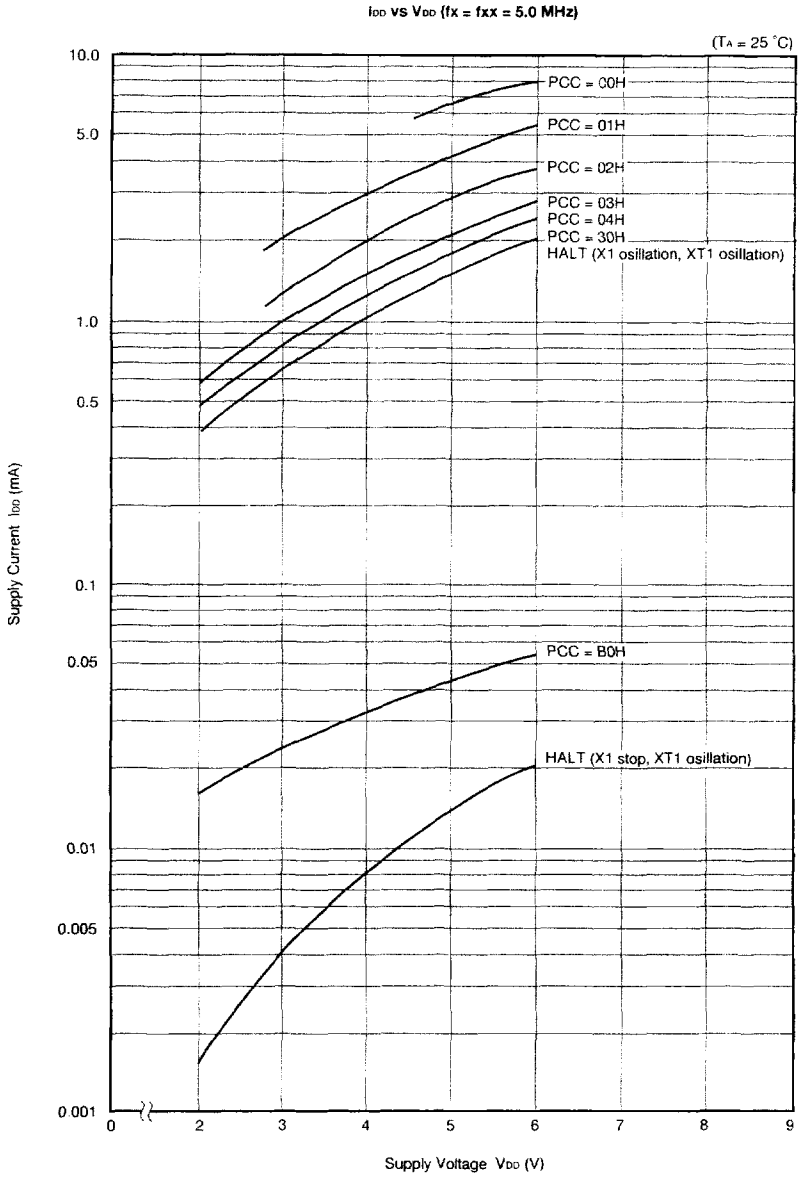
Interrupt Input Timing

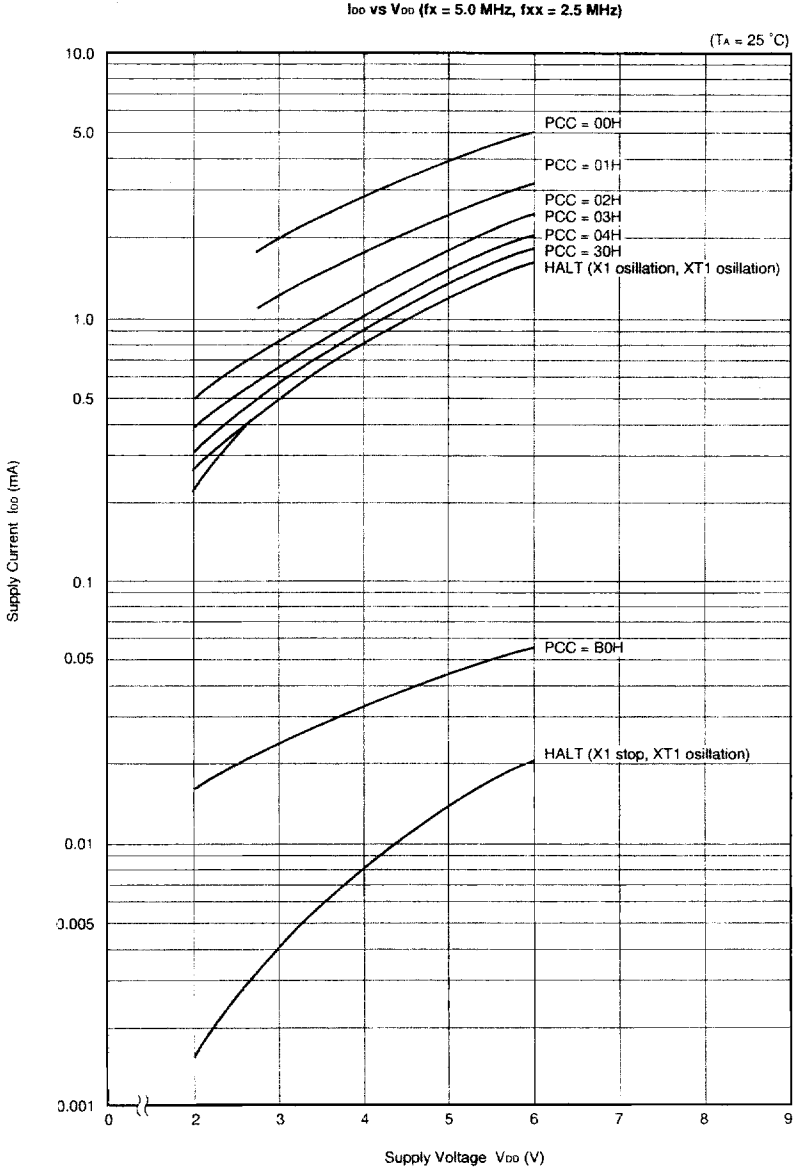


RESET Input Timing



12. CHARACTERISTIC CURVES (REFERENCE VALUE)

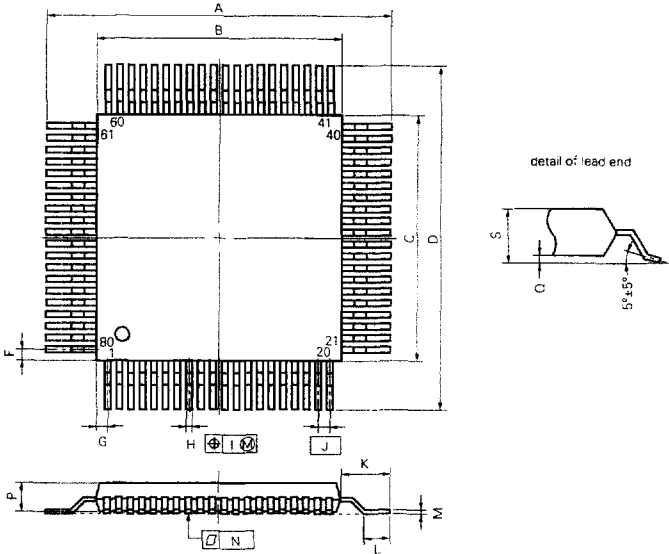




13. PACKAGE DRAWINGS

μPD78052GC-xxx-3B9, 78053GC-xxx-3B9, 78054GC-xxx-3B9, 78055GC-xxx-3B9,
 μPD78056GC-xxx-3B9, 78058GC-xxx-3B9

80 PIN PLASTIC QFP (14 × 14)



NOTE
 Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

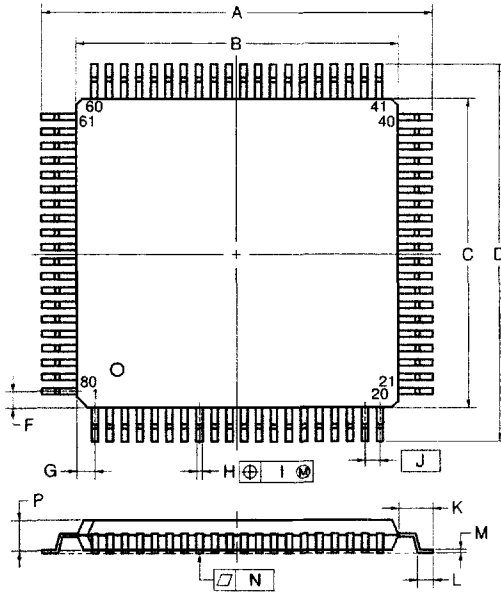
S80GC-65-3B9-3

ITEM	MILLIMETERS	INCHES
A	17.2±0.4	0.677±0.016
B	14.0±0.2	0.551 ^{+0.009} _{-0.008}
C	14.0±0.2	0.551 ^{+0.009} _{-0.008}
D	17.2±0.4	0.677±0.016
F	0.8	0.031
G	0.8	0.031
H	0.30±0.10	0.012 ^{+0.004} _{-0.005}
I	0.13	0.005
J	0.65 (T.P.)	0.026 (T.P.)
K	1.6±0.2	0.063±0.008
L	0.8±0.2	0.031 ^{+0.009} _{-0.008}
M	0.15 ^{+0.10} _{-0.05}	0.006 ^{+0.004} _{-0.003}
N	0.10	0.004
P	2.7	0.106
Q	0.1±0.1	0.004±0.004
S	3.0 MAX	0.119 MAX.

Remark Dimensions and materials of ES product are the same as those of mass-production products.

μPD78052GC-xxx-8BT, 78053GC-xxx-8BT, 78054GC-xxx-8BT, 78055GC-xxx-8BT,
 μPD78056GC-xxx-8BT, 78058GC-xxx-8BT

80 PIN PLASTIC QFP (14x14)



detail of lead end

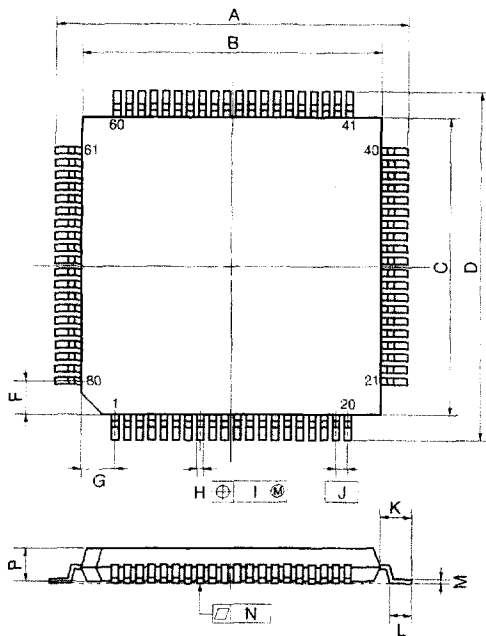
NOTE

Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	17.20±0.20	0.677±0.008
B	14.00±0.20	0.551 ^{+0.009} _{-0.008}
C	14.00±0.20	0.551 ^{+0.009} _{-0.008}
D	17.20±0.20	0.677±0.008
F	0.825	0.032
G	0.825	0.032
H	0.32±0.06	0.013 ^{+0.002} _{-0.003}
I	0.13	0.005
J	0.65 (T.P.)	0.026 (T.P.)
K	1.60±0.20	0.063±0.008
L	0.80±0.20	0.031 ^{+0.009} _{-0.008}
M	0.17 ^{+0.03} _{-0.07}	0.007 ^{+0.001} _{-0.003}
N	0.10	0.004
P	1.40±0.10	0.055±0.004
Q	0.125±0.075	0.005±0.003
R	3° ^{+7°} _{-3°}	3° ^{+7°} _{-3°}
S	1.70 MAX.	0.067 MAX.

P80GC-65-8BT

80 PIN PLASTIC TQFP (FINE PITCH) (12 × 12)



detail of lead end



NOTE

Each lead centerline is located within 0.10 mm (0.004 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	14.0±0.2	0.551 ^{+0.009} _{-0.008}
B	12.0±0.2	0.472 ^{+0.009} _{-0.008}
C	12.0±0.2	0.472 ^{+0.009} _{-0.008}
D	14.0±0.2	0.551 ^{+0.009} _{-0.008}
F	1.25	0.049
G	1.25	0.049
H	0.22 ^{+0.05} _{-0.04}	0.009±0.002
I	0.10	0.004
J	0.5 (T.P.)	0.020 (T.P.)
K	1.0±0.2	0.039 ^{+0.009} _{-0.008}
L	0.5±0.2	0.020 ^{+0.008} _{-0.009}
M	0.145 ^{+0.055} _{-0.045}	0.006±0.002
N	0.10	0.004
P	1.05	0.041
Q	0.05±0.05	0.002±0.002
R	5°±5°	5°±5°
S	1.27 MAX.	0.050 MAX.

P80GK-50-BE9-4

Remark Dimensions and materials of ES product are the same as those of mass-production products.

14. RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the conditions recommended in the table below.

For detail of recommended soldering conditions, refer to the information document "Semiconductor Device Mounting Technology Manual" (C10535E).

For soldering methods and conditions other than those recommended below, contact our sales personnel.

Table 14-1. Surface Mounting Type Soldering Conditions (1/3)

- (1) μPD78052GC-xxx-3B9 : 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
- μPD78053GC-xxx-3B9 : 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
- μPD78054GC-xxx-3B9 : 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
- μPD78055GC-xxx-3B9 : 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
- μPD78056GC-xxx-3B9 : 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)
- μPD78058GC-xxx-3B9 : 80-pin plastic QFP (14 × 14 mm, resin thickness: 2.7 mm)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
★ Infrared reflow	Package peak temperature: 235°C, Duration: 30 sec. max. (at 210°C or above), Number of times: Thrice max.	IR35-00-3
★ VPS	Package peak temperature: 215°C, Duration: 40 sec. max. (at 200°C or above), Number of times: Thrice max.	VP15-00-3
Wave soldering	Solder bath temperature : 260 °C max., Duration : 10 sec. max., Number of times : once, Preheating temperature : 120 °C max. (package surface temperature)	WS60-00-1
Partial heating	Pin temperature: 300°C max. Duration: 3 sec. max. (per device side)	—

Table 14-1. Surface Mounting Type Soldering Conditions (2/3)

- ★ (2) μPD78052GC-xxx-8BT : 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
 μPD78053GC-xxx-8BT : 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
 μPD78054GC-xxx-8BT : 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
 μPD78055GC-xxx-8BT : 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
 μPD78056GC-xxx-8BT : 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)
 μPD78058GC-xxx-8BT : 80-pin plastic QFP (14 × 14 mm, resin thickness 1.4 mm)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Package peak temperature: 235°C, Duration: 30 sec. max. (at 210°C or above), Number of times: Twice max. <Precautions> Baking cannot be applied to other than heat-resistant trays (mazine, taping, non-heat-resistant trays) when the product is wrapped.	IR35-107-2
VPS	Package peak temperature: 215°C, Duration: 40 sec. max. (at 200°C or above), Number of times: Twice max. <Precautions> Baking cannot be applied to other than heat-resistant trays (mazine, taping, non-heat-resistant trays) when the product is wrapped.	VP15-107-2
Wave soldering	Solder bath temperature: 260°C or less. Duration: 10 sec. max. Number of times: Once Preparatory heating temperature: 120°C max. (package surface temperature) Time limit: 7 days ^{Note} (thereafter 10 hours 125°C prebaking required) <Precautions> Baking cannot be applied to other than heat-resistant trays (mazine, taping, non-heat-resistant trays) when the product is wrapped.	WS60-107-1
Partial Heating	Pin temperature: 300°C max. Duration: 3 sec. max. (per device side)	—

Note For the storage period after dry-pack decompression storage conditions are max. 25 °C, 65 % RH.

Caution Use of more than one soldering method should be avoided (except in the case of partial heating).

Table 14-1. Surface Mounting Type Soldering Conditions (3/3)

- (3) μPD78052GK-xxx-BE9 : 80-pin plastic TQFP (12 × 12 mm)
- μPD78053GK-xxx-BE9 : 80-pin plastic TQFP (12 × 12 mm)
- μPD78054GK-xxx-BE9 : 80-pin plastic TQFP (12 × 12 mm)
- μPD78055GK-xxx-BE9 : 80-pin plastic TQFP (12 × 12 mm)
- μPD78056GK-xxx-BE9 : 80-pin plastic TQFP (12 × 12 mm)
- μPD78058GK-xxx-BE9 : 80-pin plastic TQFP (12 × 12 mm)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
★ Infrared reflow	Package peak temperature: 235°C, Duration: 30 sec. max. (at 210°C or above), Number of times: Thrice max., Time limit: 7 days ^{Note} (thereafter 10 hours 125 °C prebaking required) <Precautions> Baking cannot be applied to other than heat-resistant trays (magazine, taping, non-heat-resistant trays) when the product is wrapped.	IR35-107-3
★ VPS	Package peak temperature: 215°C, Duration: 40 sec. max. (at 200°C or above), Number of times: Thrice max., Time limit: 7 days ^{Note} (thereafter 10 hours 125 °C prebaking required) <Precautions> Baking cannot be applied to other than heat-resistant trays (magazine, taping, non-heat-resistant trays) when the product is wrapped.	VP15-107-3
Partial Heating	Pin temperature: 300°C max. Duration: 3 sec. max. (per device side)	—

Note For the storage period after dry-pack decompression storage conditions are max. 25 °C, 65 % RH.

Caution Use of more than one soldering method should be avoided (except in the case of partial heating).